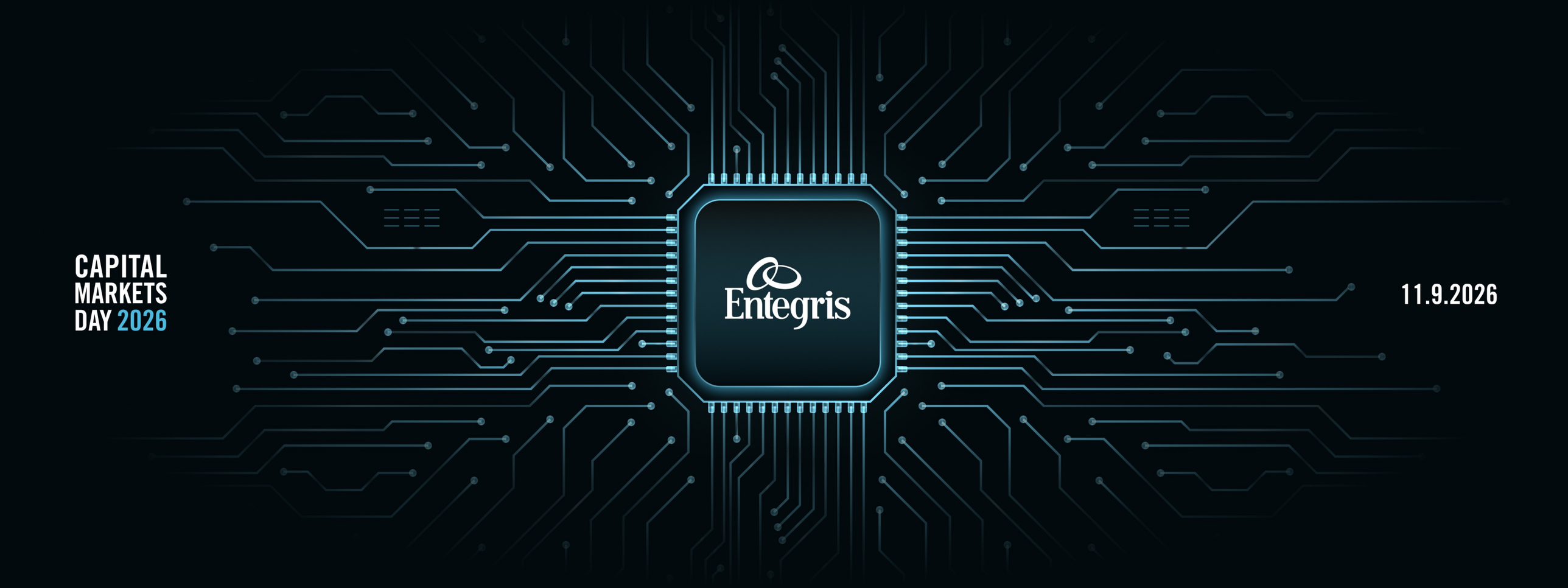

CAPITAL
MARKETS
DAY 2026
Entegris
11.9.2026

JEFFREY SCHNELL

Vice President, Investor Relations

ENTEGRIS CAPITAL MARKETS DAY 2026

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AGENDA

WELCOME	Jeffrey Schnell
ENTEGRIS: UNIQUELY POSITIONED FOR THE AI ERA	David Reeder
MATERIALS INNOVATION ENABLING NEXT-GENERATION COMPUTING	Olivier Blachier
BREAK	
ADVANCED PURITY ENABLING YIELD AND SCALE	Clint Haris
COMPOUNDING GROWTH, PROFITABILITY, AND SHAREHOLDER VALUE	Sukhi Nagesh
Q&A	
CLOSING REMARKS	David Reeder

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SAFE HARBOR

This presentation and the accompanying oral remarks of management of Entegris, Inc. (the "Company"), including responses to questions, contain "forward-looking statements", including statements about the Company's long-term financial targets, strategy and market outlook. The words "believe," "expect," "anticipate," "intend," "estimate," "forecast," "project," "should," "may," "will," "would" or the negative thereof and similar expressions are intended to identify such forward-looking statements. These forward-looking statements are based on current management expectations and assumptions only as of the date of this presentation. They are not guarantees of future performance and they involve substantial risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from the results expressed in, or implied by, these forward-looking statements. Market size, growth and other industry data in this presentation come from independent third parties and the Company's own estimates. This data involves assumptions and limitations, and the Company has not independently verified third-party data or guaranteed its accuracy or completeness. Industry forecasts are subject to the risks below. These risks and uncertainties include, but are not limited to, the Company's ability to execute its strategic plan and achieve its long-term financial targets, which are based on assumptions about semiconductor industry growth, market share, pricing, costs and capital spending that may prove incorrect; fluctuations in the demand for semiconductors and the overall volume of semiconductor manufacturing; the impact of global economic uncertainty, including financial market volatility, which may result in lower consumer spending, inflationary pressures, a higher interest rate environment, an economic recession, and bank instability; supply chain interruptions and the Company's dependence on sole, single, and limited source suppliers and related raw material shortages and cost increases; operational, political, legal and other risks associated with the Company's international operations, including challenges in hiring and integrating workers in different countries, maintaining appropriate business practices across the varied jurisdictions in which the Company operates, and engaging and managing global, regional and local third-party service providers; risks related to geopolitical uncertainty and regional and global instabilities and hostilities, including, but not limited to, the ongoing conflicts between Ukraine and Russia, and conflicts in the Middle East, as well as the global responses thereto; export controls, economic sanctions, and similar restrictions; the concentration and consolidation of the Company's customer base; the Company's ability to meet rapid demand shifts; the Company's ability to continue technological innovation and to introduce new products to meet customers' rapidly changing requirements; manufacturing and other operational disruptions or delays; the Company's ability to complete, ramp and achieve expected utilization of new and expanded manufacturing capacity; IT system failures, network disruptions, and cybersecurity risks; tariffs, additional taxes and other protectionist measures resulting from international trade disputes, strained international relations and changes in foreign and national security policy; the risks associated with the use and manufacture of hazardous materials; goodwill impairment; challenges in attracting and retaining qualified personnel; the Company's ability to protect and enforce intellectual property rights; artificial intelligence; the Company's environmental, social, and governance commitments; legal and regulatory risks, including changes in laws and regulations related to the environment, health and safety, accounting standards, and corporate governance, across the jurisdictions in which the Company operates; changes in taxation or adverse tax rulings; the ability to obtain government incentives and the possibility that competitors will benefit from government incentives for which the Company does not qualify; the amount and consequences of the Company's indebtedness, the Company's ability to repay its debt and to obtain future financing, and the Company's obligations under its current outstanding credit facilities; the Company's ability to achieve its capital allocation and deleveraging objectives; volatility in the Company's stock price; the payment of cash dividends and the adoption of future share repurchase programs; the Company's ability to effectively implement any organizational changes; substantial competition; the Company's ability to identify, complete and integrate acquisitions, joint ventures, divestitures or other similar transactions; the impacts of climate change; and other matters. These risks and uncertainties also include, but are not limited to, the risk factors and additional information described in the Company's Annual Report on Form 10-K for the fiscal year ended December 31, 2025, filed with the Securities and Exchange Commission (the "SEC") on February 11, 2026, including under the heading "Risk Factors" in Item 1A, in the Company's subsequent Quarterly Reports on Form 10-Q, and in the Company's other periodic filings with the SEC. Except as required under the federal securities laws and the rules and regulations of the SEC, the Company undertakes no obligation to update any forward-looking statements or information contained herein or made orally during this event, which speak only as of their respective dates. Any replay or archived webcast of this event speaks only as of November 9, 2026.

This presentation contains references to "Adjusted EBITDA," "Adjusted EBITDA – as a % of Net Sales," "Adjusted Operating Income," "Adjusted Operating Margin," "Adjusted Gross Profit," "Adjusted Gross Margin – as a % of Net Sales," "Adjusted Segment Profit," "Adjusted Segment Profit Margin," "Non-GAAP Operating Expenses," "Non-GAAP Tax Rate," "Non-GAAP Net Income," "Diluted Non-GAAP Earnings per Common Share," "Free Cash Flow," and other measures that are not presented in accordance with U.S. generally accepted accounting principles ("GAAP"). Management uses these non-GAAP financial measures to evaluate the Company's operating and financial performance and for planning purposes, and believes they provide investors with useful supplemental information and facilitate period-to-period comparisons by excluding items that management does not consider indicative of the Company's ongoing operating performance. The non-GAAP financial measures should not be considered in isolation or as a substitute for GAAP financial measures but should instead be read in conjunction with the GAAP financial measures. Non-GAAP financial measures have limitations: they do not reflect all of the amounts associated with the Company's results as determined in accordance with GAAP, the excluded items may recur and may have a material impact on the Company's reported results, and other companies may calculate similarly titled measures differently, which may limit their usefulness as comparative measures. Further information with respect to and reconciliations of such historical measures, and of the estimated 2026 non-GAAP financial measures presented, to the most directly comparable GAAP measure can be found in the appendix to this presentation and on the Company's investor relations website at investor.entegris.com. The Company does not provide a reconciliation of the forward-looking non-GAAP financial measures reflected in its long-term financial targets to the most directly comparable GAAP measures because certain items excluded from these non-GAAP measures, such as restructuring, acquisition-related and impairment charges, cannot be reasonably predicted or estimated without unreasonable efforts due to their inherent uncertainty. These items could be material, individually or in the aggregate, to the Company's future GAAP results.

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TODAY'S SPEAKERS

Uniquely Positioned for the AI Era



DAVID REEDER
President & CEO

Materials Innovation Enabling Next-Generation Computing



OLIVIER BLACHIER
President, Materials Solutions & SVP, Chief Innovation Officer

Advanced Purity Enabling Yield & Scale



CLINT HARIS
SVP & President, Advanced Purity Solutions

Compounding Growth, Profitability, and Shareholder Value



SUKHI NAGESH
SVP, CFO

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DAVID REEDER

President & CEO

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WHY ENTEGRIS?

ENTEGRIS: UNIQUELY POSITIONED FOR THE AI ERA

WHO WE ARE

Leading pure-play semiconductor materials and purity platform

WHERE WE COMPETE

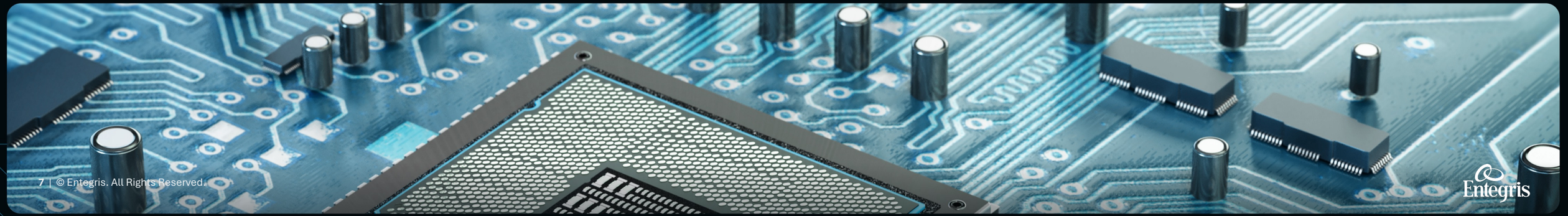
Differentiated through-cycle growth model

MARKET OPPORTUNITY

AI is creating an unprecedented opportunity

HOW WE WIN

Rising materials and purity content compounds Entegris growth



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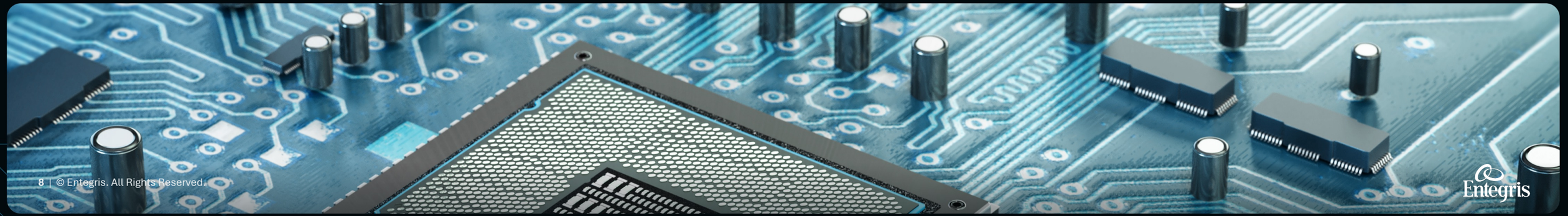
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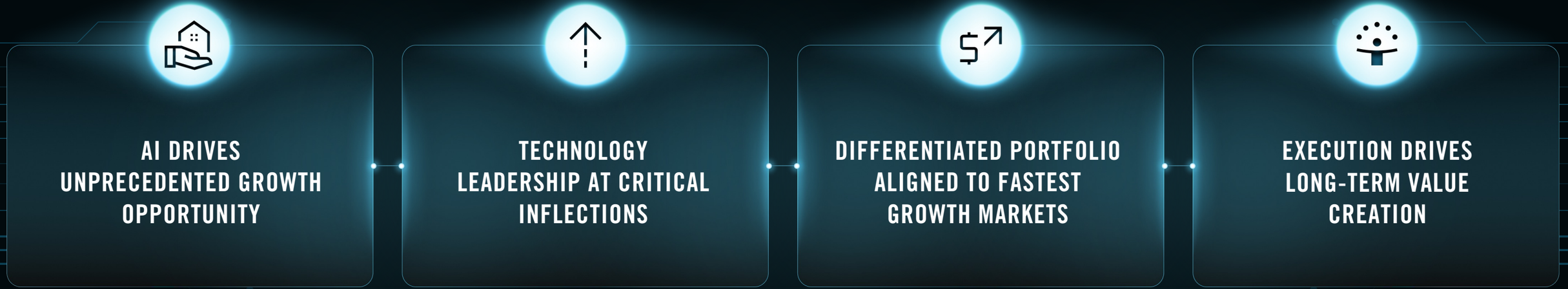
HOW WE WIN

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ENTEGRIS: THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM



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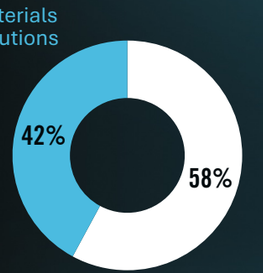
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ENTEGRIS: THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM

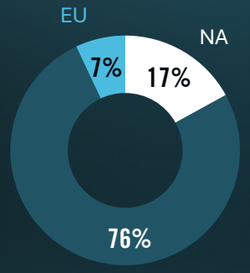
LTM REVENUE SNAPSHOT (AS OF 3Q 2026)

$3.5B

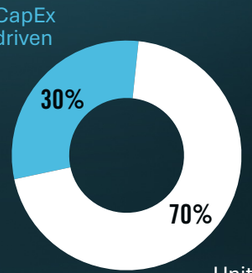
SEGMENTS



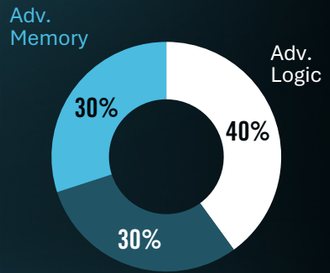
REGIONS



TYPE[1]



END MARKETS[1]



Enabling semiconductor technology inflections	Unmatched breadth and scale	Mission critical to enhance performance and yield	Positioned in highest-growth end markets	Accelerating growth, profitability and cash flow
#1-2 Position across key product categories	**>4K** Active patents	**35** Manufacturing sites	**4** Technology centers	**~9K** Employees globally

1. Percentages are approximate and based on management estimates, and exclude non-semiconductor revenue, which represents approximately 5% of LTM net sales.

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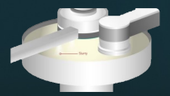
ENTEGRIS IS CRITICAL TO THE SEMICONDUCTOR ECOSYSTEM

MATERIALS SOLUTIONS

Critical materials enable performance, node transitions, and reduce cost of ownership



Deposition



CMP



Specialty Materials

ADVANCED PURITY SOLUTIONS

Purity and contamination control across the fab enhance yield



Filtration



Purification



FOUPs

tsmc · SAMSUNG · SK hynix · intel · Micron · ASML · APPLIED MATERIALS · Lam RESEARCH · Texas Instruments · Infineon · TEL TOKYO ELECTRON

KLA · STMicroelectronics · KIOXIA · SMIC · UMC · GlobalFoundries · Shin-Etsu · onsemi · SCREEN · Linde

华虹集团 HUAHONG GROUP · HHGrace · FUJIFILM · BASF We create chemistry · PSMC · GTA 积塔半导体 GTA Semiconductor · SPTS Semiconductor Technologies & Instruments · MEC · CMT GLOBAL · Rapidus

Note: Non-exhaustive list of semiconductor ecosystem.

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WHY ENTEGRIS?

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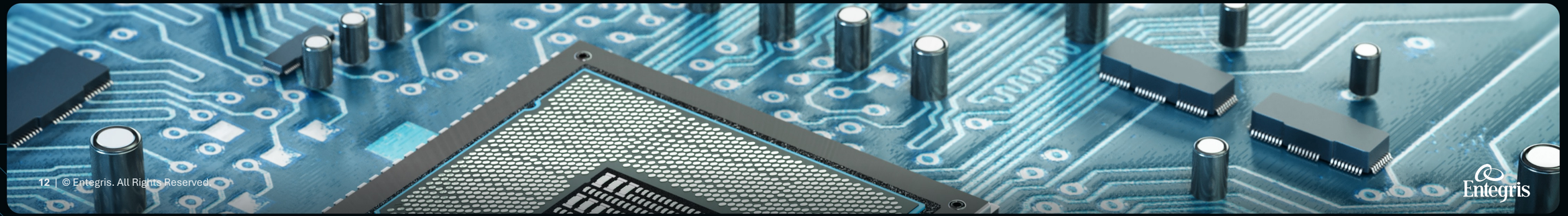
Differentiated through-cycle growth model

MARKET OPPORTUNITY

AI is creating an unprecedented opportunity

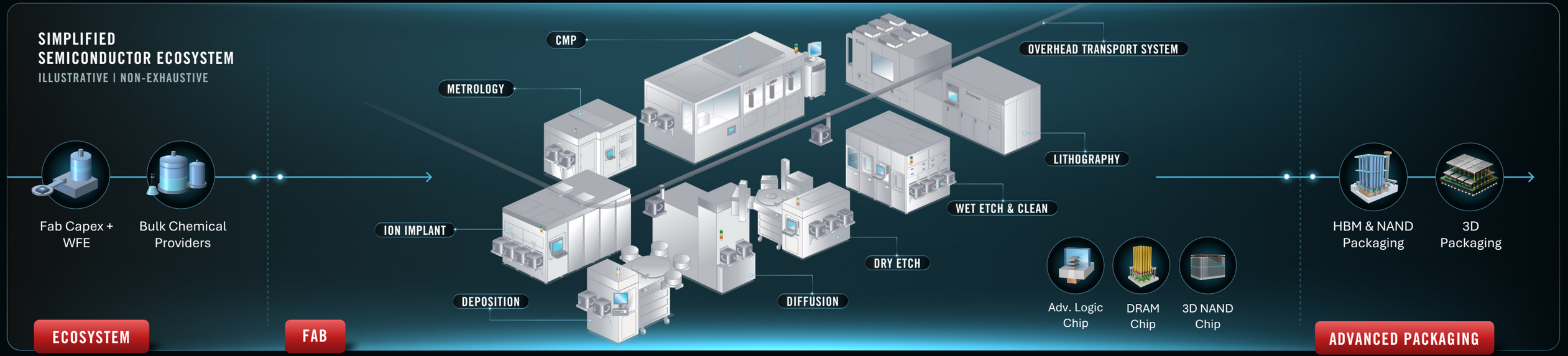
HOW WE WIN

Rising materials and purity content compounds Entegris growth



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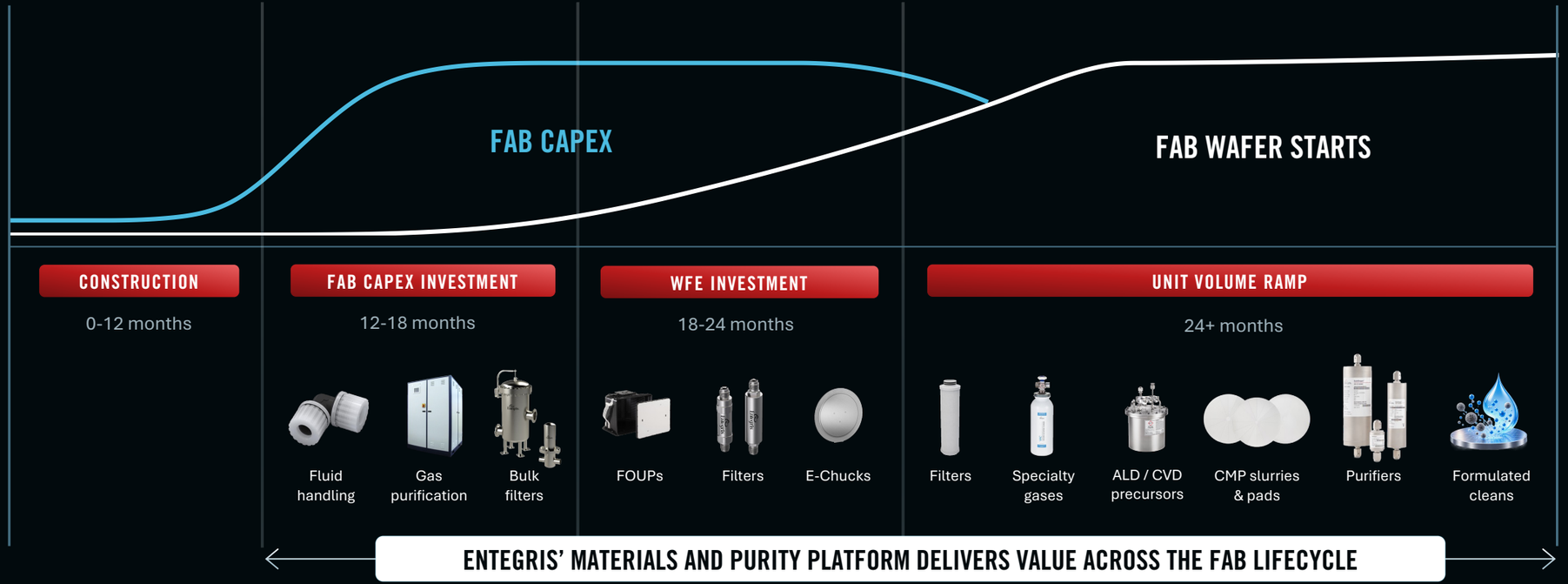
A TECHNOLOGY PORTFOLIO THAT COVERS THE ENTIRE SEMICONDUCTOR ECOSYSTEM



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ENTEGRIS' UNIQUE THROUGH-CYCLE GROWTH MODEL



Note: Conceptual visualization of the full fab life cycle, non-exhaustive.

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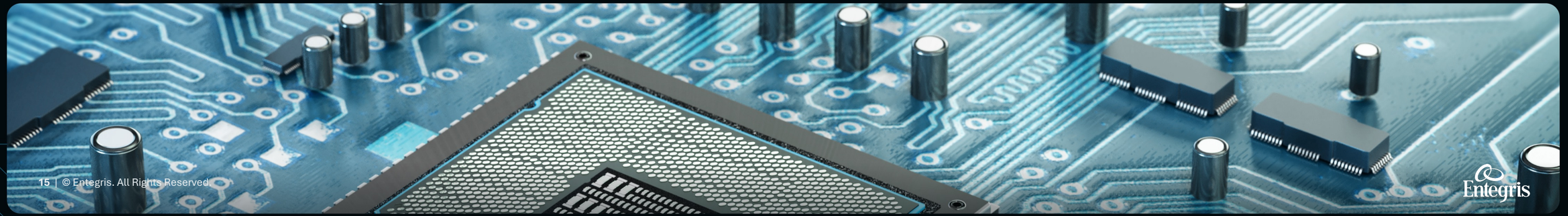
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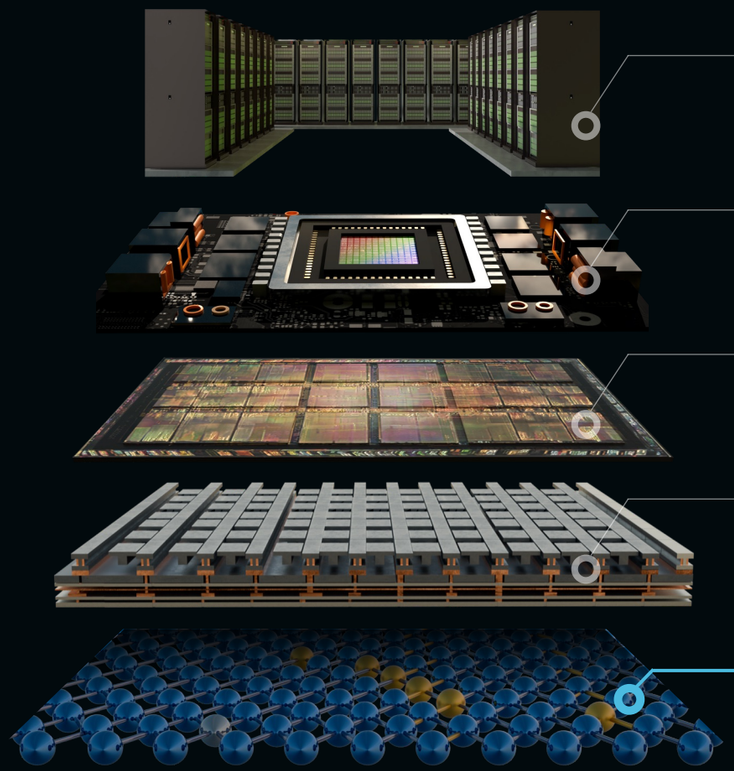
HOW WE WIN

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THE SEMICONDUCTOR PROCESS BEGINS WITH ENTEGRIS



SYSTEM LEVEL

Compute capacity is compromised

CHIP LEVEL

Performance and reliability degrade

WAFER LEVEL

Specifications fail and yield declines

TRANSISTOR LEVEL

Defects compound

SEMICONDUCTORS DEMAND MOLECULAR-SCALE PRECISION

Enabled by Entegris' materials and purity platform

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THE ECOSYSTEM[1] IS ENABLED BY ENTEGRIS

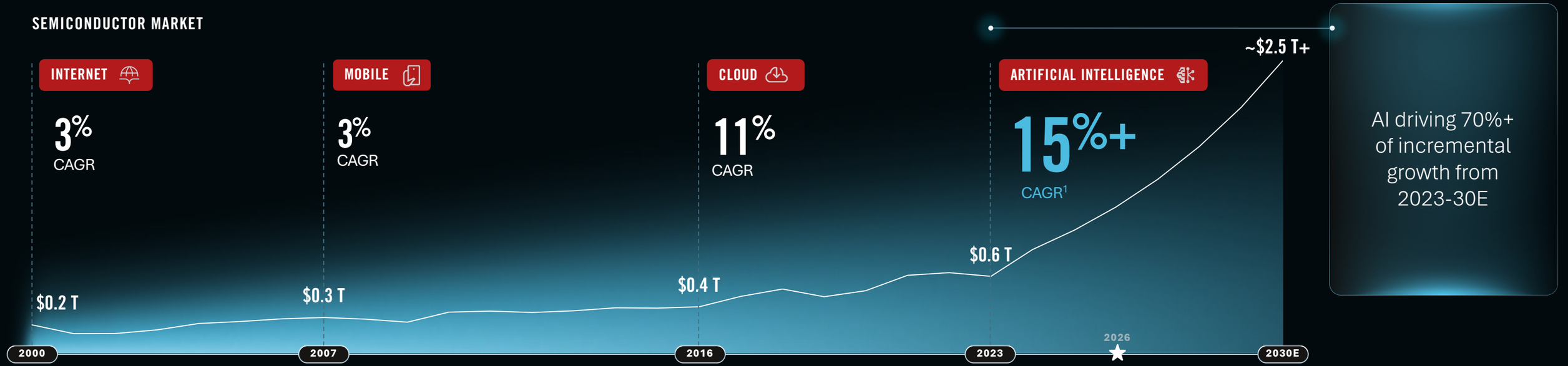


Source: Omdia, Yole, SEMI, Entegris. 1. 2026E market size. Note: The trademarks, logos, and trade names of third parties displayed in this presentation are the property of their respective owners and are used for identification purposes only. Their inclusion does not imply any affiliation with, endorsement of, or commercial relationship with Entegris, Inc. by any such third party.

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AI IS RESHAPING THE SEMICONDUCTOR GROWTH TRAJECTORY

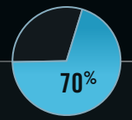


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Source: Semiconductor market size and growth projections reflect estimates from McKinsey Semiconductor Demand model, Omdia AMFT, Gartner, and Entegris and are subject to change. Actual results may differ materially. 1. 2026-2030E industry revenue CAGR.

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SERVED AVAILABLE MARKET GROWING ~10% CAGR[1]



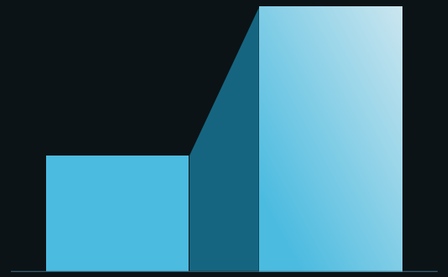
MSI SEGMENTS	MSI SUBSEGMENT CAGR[1]
Advanced Logic (7nm and below)	~11%
Advanced Memory	~7%
Mainstream Logic	~3%

+



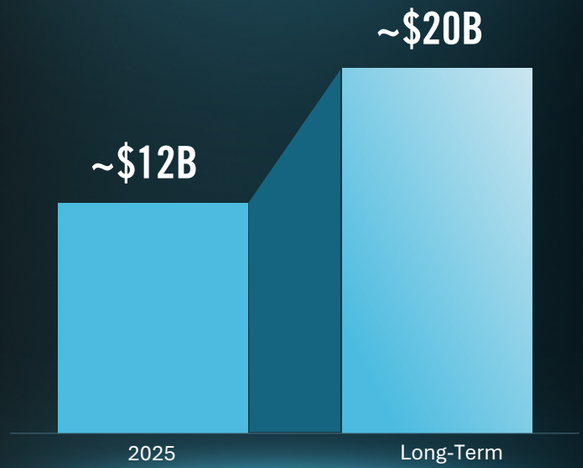
FAB CAPEX + WFE EQUIPMENT
$B

>20% CAGR[1]



ENTEGRIS SAM
$B

~10% CAGR[1]

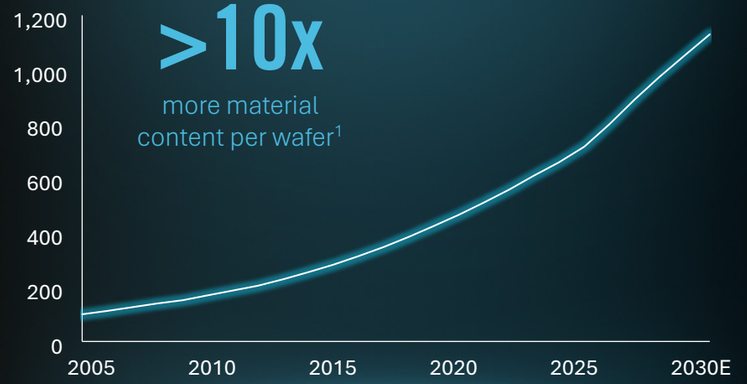


1. Long-Term (3-5 years).

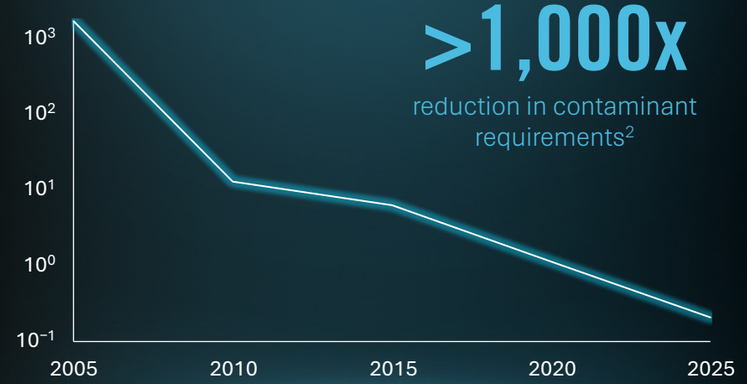
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TECHNOLOGY TRANSITIONS CREATING POWERFUL TAILWINDS FOR ENTEGRIS

MATERIALS CONTENT PER WAFER IS ACCELERATING



CONTAMINATION CONTROL LIMITS ARE TIGHTENING



New architectures and process flows are increasing materials intensity

Contamination control limits driving the need for higher purity

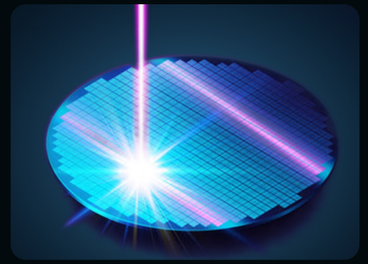
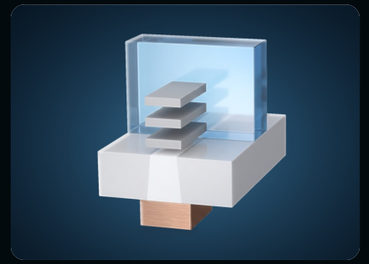
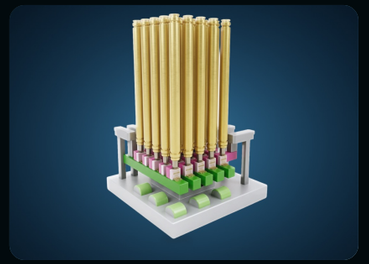
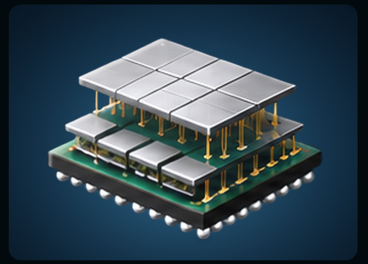
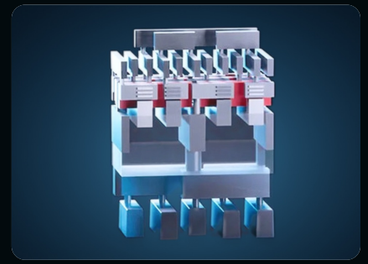
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Source: IMEC, IRDS, TSMC, SEMI, ITRS, Entegris (ppt, log scale).

1. Materials intensity per 300mm wafer (Index 90nm planar CMOS =100);

2. Representative Airborne Molecular Contamination (AMC) concentration of concern

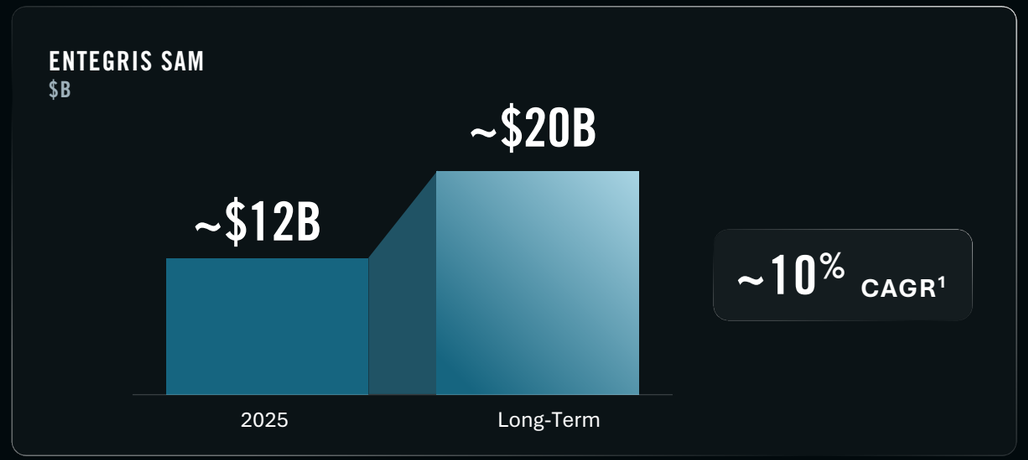
TECHNOLOGY ROADMAPS CREATING OPPORTUNITIES FOR ENTEGRIS

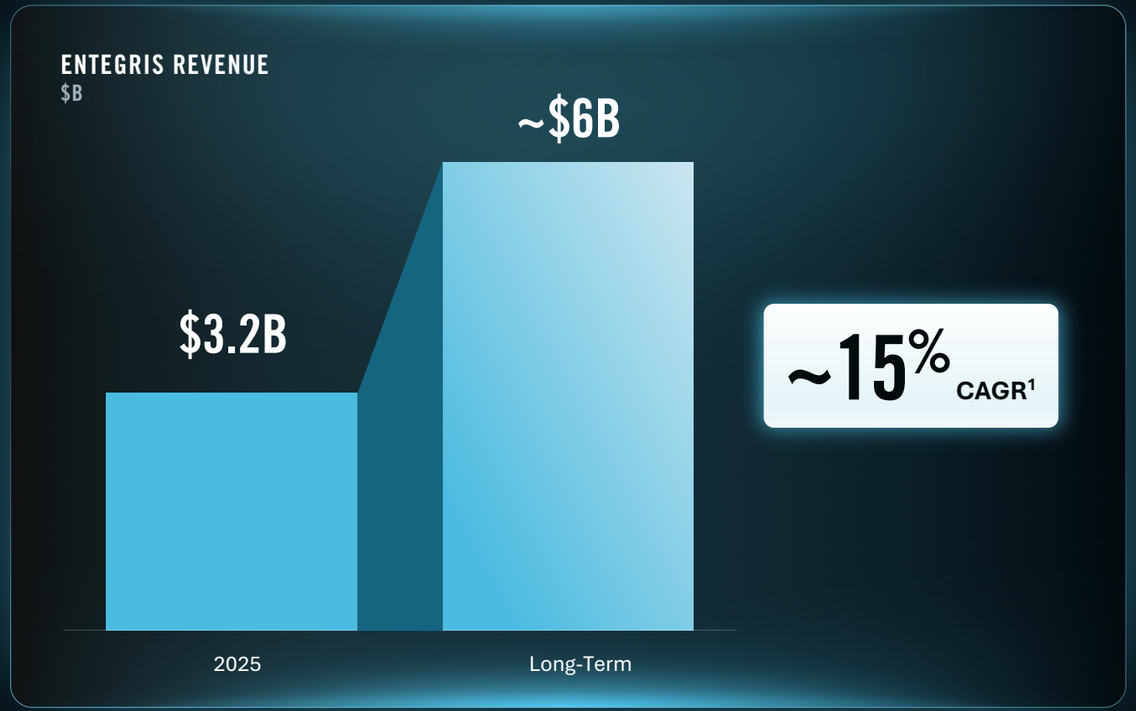
EUV	GATE ALL AROUND BACKSIDE POWER NETWORK	3D NAND 4F2 / 3D DRAM	ADVANCED PACKAGING	SILICON PHOTONICS DATACENTER POWER IC	CFET
					
Dry resist	CMP	Dry/Wet etch	CMP/CVD	SiC/GaN CMP	ASD/ALE
EUV pod	ALD/CVD	ALD/CVD	New carrier	High-viscosity pump	CMP
Filtration	Selective etch	CMP	TIM	Filtration	ALD/CVD

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TECHNOLOGY TRANSITIONS ENABLING ENTEGRIS TO ACCELERATE GROWTH





1. Long-Term (3-5 years).

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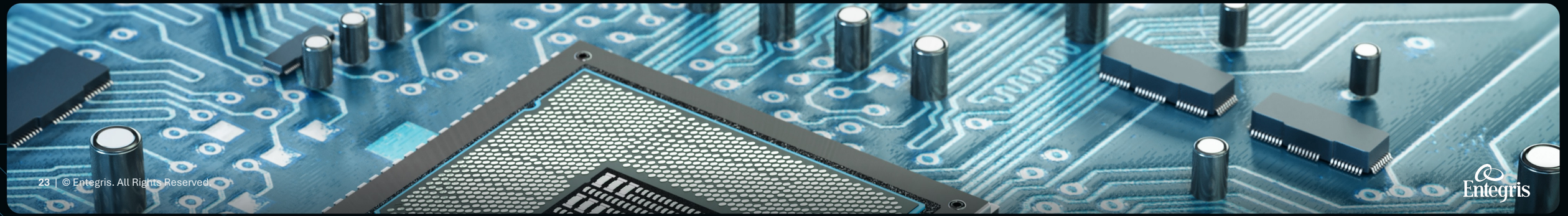
Differentiated through-cycle growth model

MARKET OPPORTUNITY

AI is creating an unprecedented opportunity

HOW WE WIN

Rising materials and purity content compounds Entegris growth



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OUR TRANSFORMATION CONVERTS OPPORTUNITY INTO RESULTS

THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM

CUSTOMER

ELEVATE CUSTOMER CENTRICITY

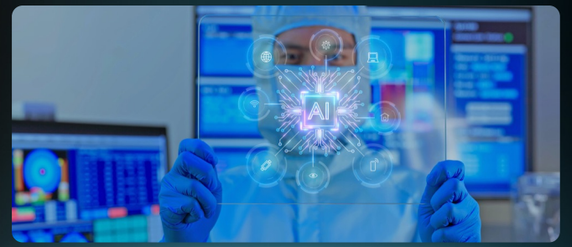
Accelerate growth



TECHNOLOGY

EXTEND TECHNOLOGY LEADERSHIP

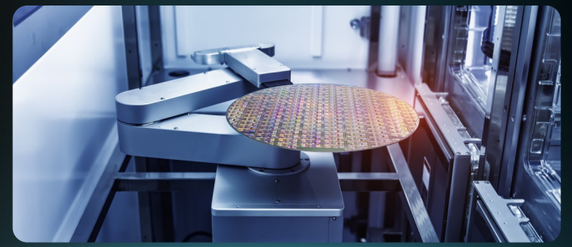
Advance innovation through AI



OPERATIONS

STRATEGIC OPERATING SCALE

Create competitive advantage



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CUSTOMER

EARLIER ENGAGEMENT AND INTEGRATED SOLUTIONS INCREASE DIFFERENTIATION

STRATEGIC ACCOUNT MANAGEMENT & PLANNING

ENGAGE EARLIER

Engage at pathfinding to shape roadmaps

From: N+1 → To: N+2 / N+3

DEVELOP FASTER

AI-based simulation to design and test solutions

From: multi-day analytical lab testing → To: AI/ML-based pre-validated models

INCREASING CRITICALITY TO CUSTOMERS

INTEGRATED SALES ENABLEMENT

SOLVE HOLISTICALLY

In- and cross-module synchronization for integrated solutions

From: sequential → MOLECULE + CLEANS + FILTERS + OTHERS → To: cross-module

CROSS-MODULE SOLUTIONS

PROCESS SOLUTIONS

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TECHNOLOGY

WE HAVE AMASSED A STRONG TECHNOLOGY PORTFOLIO AND BUILT MANUFACTURING SCALE

APRIL 2014

ATMI

Advanced materials and material delivery systems

APRIL 2017

Trinzik™ product line

Water and chemical filtration

JANUARY 2018

Particle Sizing Systems

Particle sizing instrumentation for liquid applications

JUNE 2018

SAES Pure Gas

Bulk gas purification systems

MARCH 2019

Digital Specialty Chemicals

Organometallics and other fine chemicals

JULY 2019

MPD Chemicals

Organosilanes and other advanced chemicals

SEPTEMBER 2019

Hangzhou Anow Microfiltration

Filtration manufacturing in China

JANUARY 2020

Sinmat

CMP, Slurries for SiC, GaN C

JULY 2020

GMTI and CRP

Advanced process monitoring for CMP chemistries

NOVEMBER 2021

BASF's Precision Microchemical business

CMP Slurries for SiC and high purity cleaners for HDD

JULY 2022

CMC Materials

Industry-leading CMP slurries and pads

2023

KSP & Rockrimmon expansion

In-region, for region strategy

2026

Advanced Abrasives

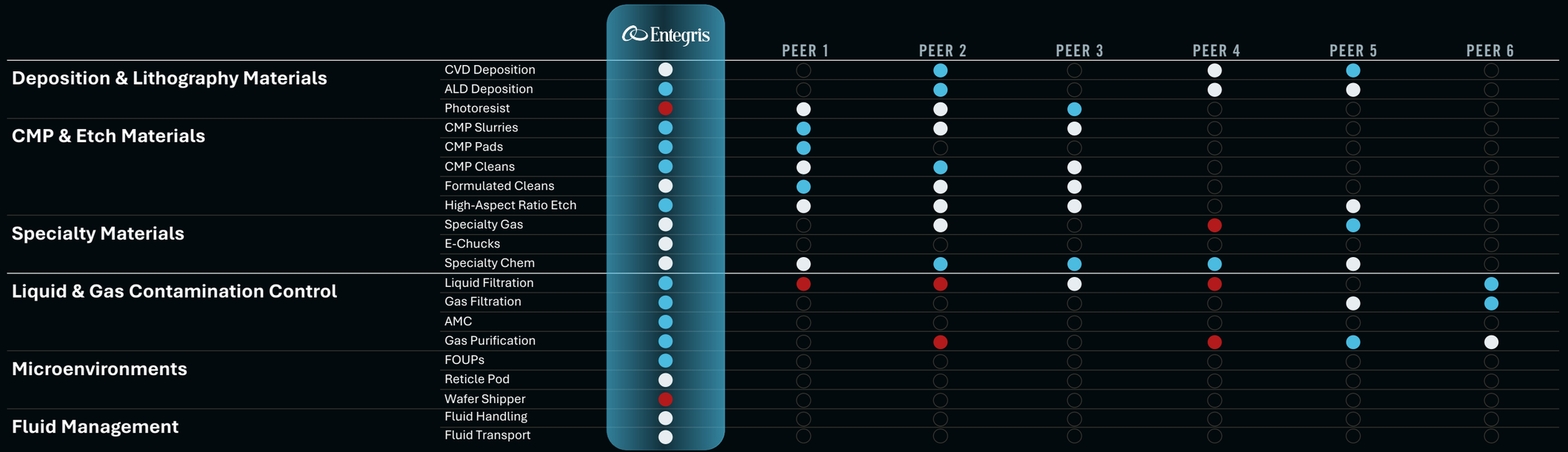
Technology-leading diamond abrasives

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TECHNOLOGY

LEADERSHIP POSITIONS IN CRITICAL SEMICONDUCTOR CATEGORIES



MARKET POSITION

- Leading
- Top 5
- Under-represented

Source: Management internal assessments and publicly available information.

Note: List of peers, technologies and solutions is illustrative and non-exhaustive.

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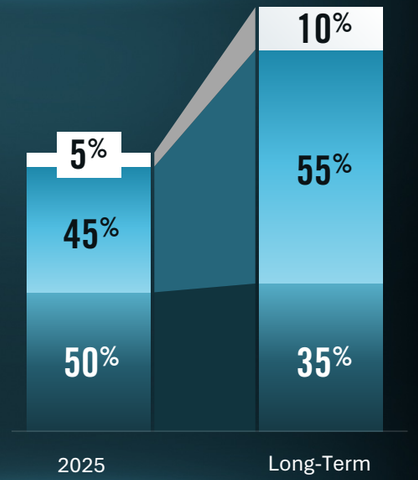
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TECHNOLOGY

FOCUSED INVESTMENTS IN INNOVATION WILL EXTEND OUR TECHNOLOGY LEADERSHIP

ER&D[1] SPEND BY FOCUS
%

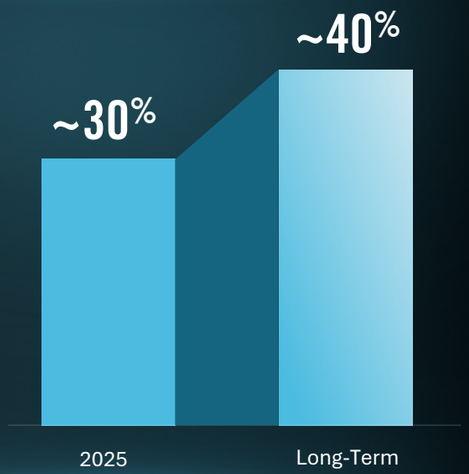
Shifting ER&D towards higher growth opportunities



- New technologies
- SAM expansion
- Existing SAM

VITALITY INDEX[2]
%

New product revenue as % of total revenue



~3x MORE EFFICIENT INNOVATION CYCLES ENABLED BY AI

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1. See GAAP to non-GAAP reconciliation tables in the appendix of this presentation. Long-term (3-5 years). 2. Revenue from products released in the last 5 years as % of total on a consolidated level. Long-term (3-5 years).

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OPERATIONS

LEVERAGING SCALE TO IMPROVE PERFORMANCE, RESILIENCE, AND PROFITABILITY

NETWORK OPTIMIZATION

Simplify footprint, localize supply, drive critical mass

YIELD ENHANCEMENT

Increase manufacturing yield and reduce scrap/waste



STRATEGIC SUPPLY MANAGEMENT

Leverage enterprise scale & consolidate strategic suppliers

PRODUCTIVITY IMPROVEMENT

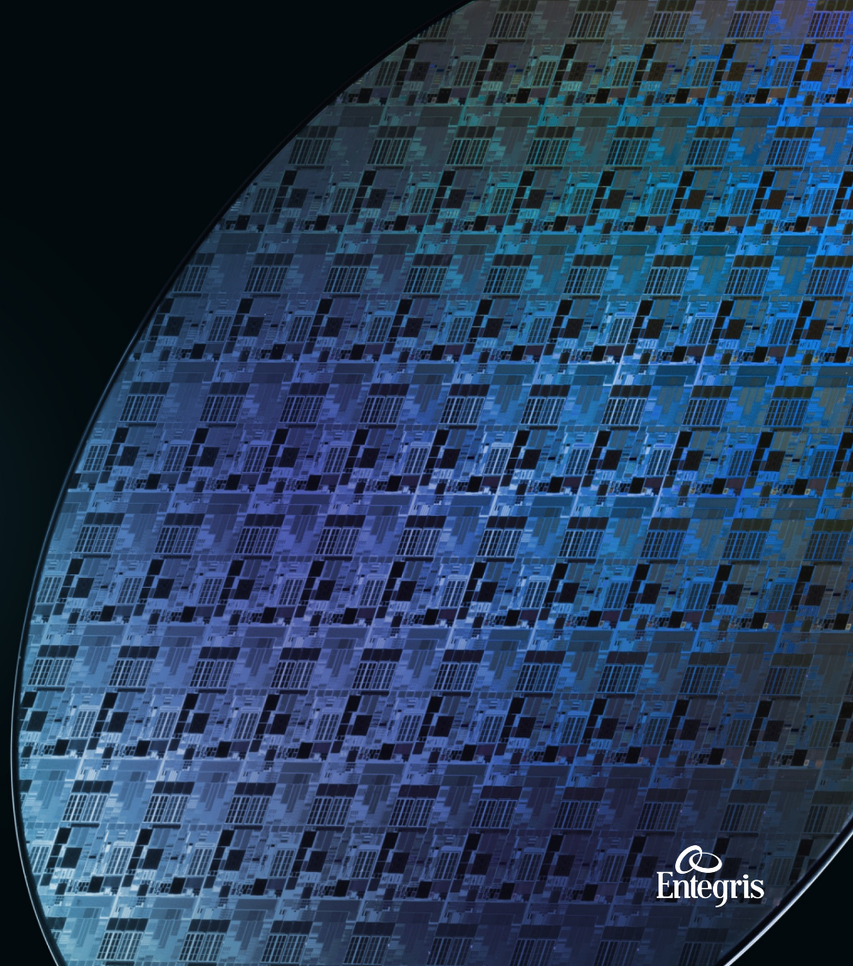
Maximize utilization and reduce cycle time

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ENTEGRIS' GROWTH ALGORITHM

AI DEVICE COMPLEXITY + TECHNOLOGY SOLUTIONS + DISCIPLINED EXECUTION = ~15% GROWTH CAGR[1]



1. Long-Term (3-5 years).

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OLIVIER BLACHIER

President, Materials Solutions &
SVP, Chief Innovation Officer

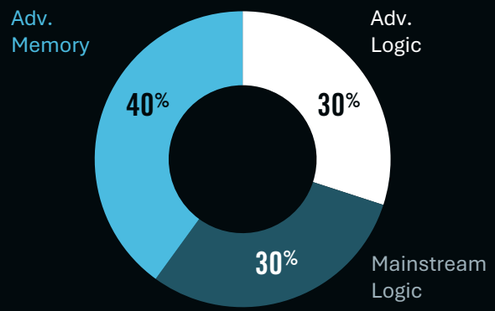
MATERIALS INNOVATION ENABLING NEXT-GENERATION COMPUTING

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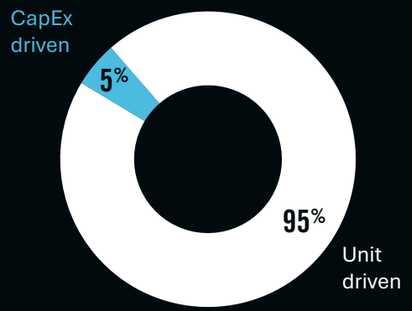
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~$1.5B MATERIALS PLATFORM AT THE HEART OF SEMICONDUCTOR SCALING

REVENUE BY END MARKET[1]
LTM



REVENUE BY TYPE[1]
LTM

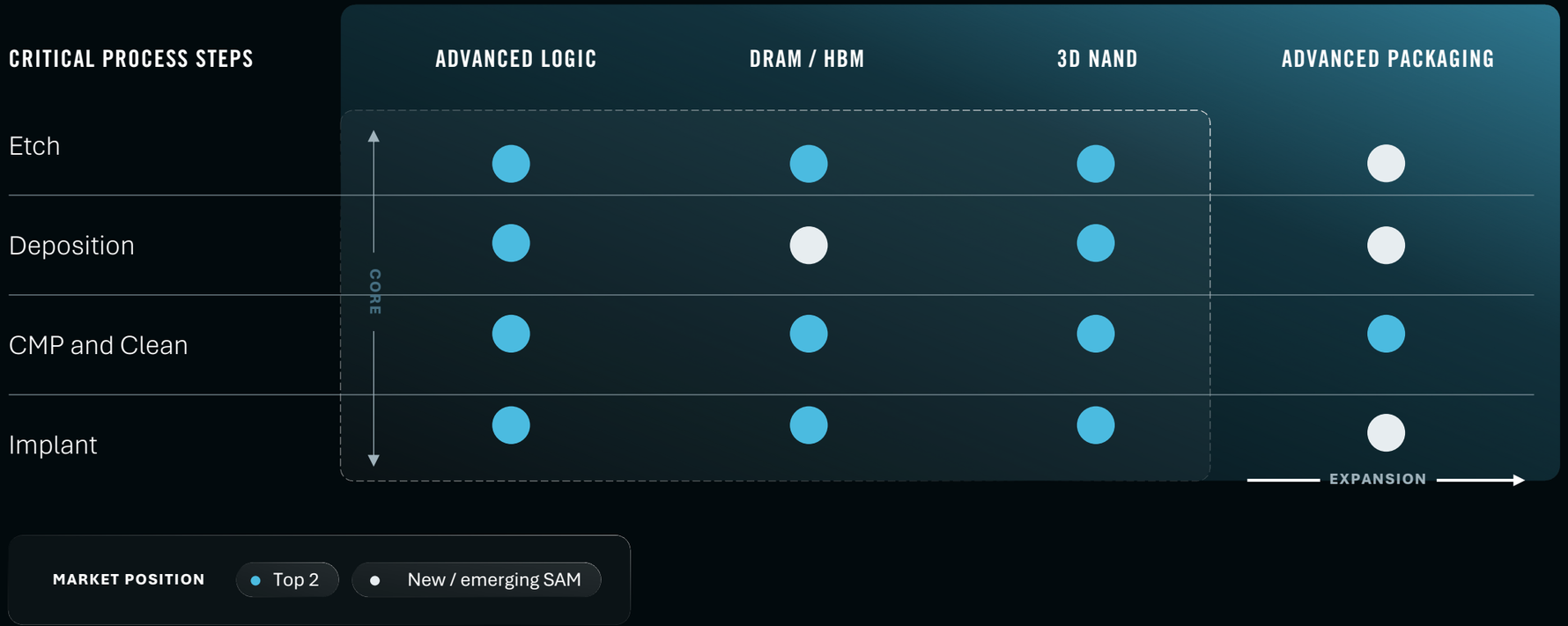


ADVANCED DEPOSITION & MATERIALS ENGINEERING	DEPOSITION MATERIALS	IMPLANT / SPECIALTY GASES	COATINGS / E-CHUCKS / GRAPHITE
SELECTIVE ETCHANTS & SURFACE ENGINEERING	SELECTIVE ETCH	PERR	SPEC CHEMICALS
PLANARIZATION & SURFACE INTEGRATION	SLURRIES	CMP PADS	CMP CLEANS
ADVANCED SUBSTRATES & INTEGRATION MATERIALS	ADV. SUBSTRATES	THERMAL INTERFACE MATERIALS	HYBRID BONDING

1. Percentages are approximate and based on management estimates, and exclude non-semiconductor revenue, which represents approximately 5% of LTM net sales.

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EVERY MAJOR DEVICE TRANSITION CREATES MULTIPLE GROWTH OPPORTUNITIES



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AI-ERA ARCHITECTURES CAN NEARLY DOUBLE MATERIALS CONTENT PER WAFER

	TECHNOLOGY	BASELINE	MATERIAL CONTENT PER WAFER	NEAR-TERM INFLECTION	MATERIAL CONTENT PER WAFER	LONG-TERM INFLECTION
1	 Adv. Logic	FinFET	+50%	GAA	↑	CFET
2	 DRAM / HBM	$6F^2$ / HBM4	+40%	$4F^2$ / HBM5	↑	3D DRAM
3	 3D NAND	300 layers	+90%	500-1000 layers	↑	Novel memory
4	 Adv. Packaging	2.5D[1]	+70%	3D + large format	↑	System-level[2]

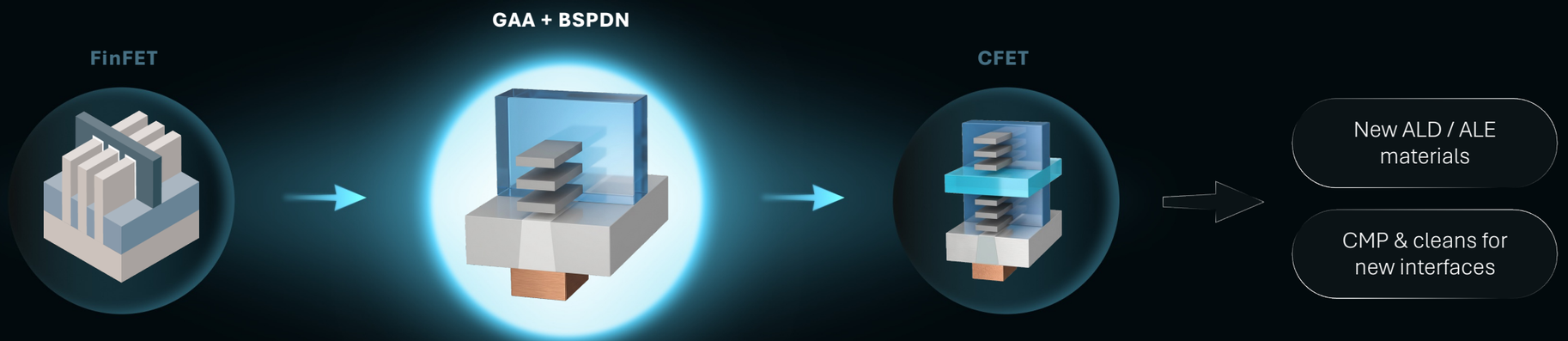
Source: Lam, UC Berkeley, IBM, IEEE, Entegris. 1. CoWoS / EMIB / SoIC / Foveros. 2. Panel-level / Glass / CPO / Advanced 3D.

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1 ADVANCED LOGIC: +50% MORE CONTENT PER WAFER & NEW SAMS

TECHNOLOGY INFLECTIONS



New ALD / ALE materials

CMP & cleans for new interfaces

130+ Engagements

POR WINS

- Dielectrics and Metals CMP solutions
- Area Selective Depositions

NEW SAM EXPANSION

- Next-Generation Metal-Oxide Resist
- Highly Selective Dielectrics Etchant
- FEOL Dielectrics & New Metals

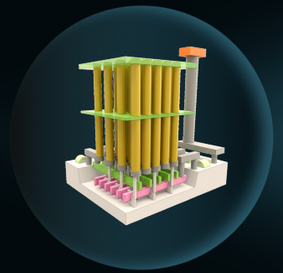
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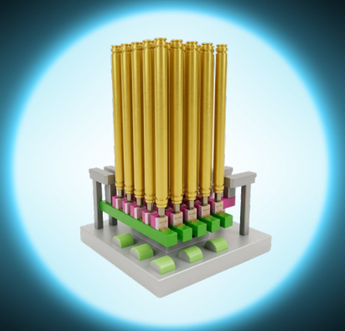
2 ADVANCED MEMORY: +40% MORE CONTENT PER WAFER & NEW SAMS

TECHNOLOGY INFLECTIONS

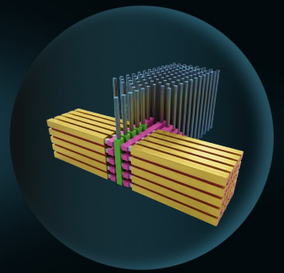
HBM4&4E / $6F^2$



HBM5&5E / $4F^2$



HBM6&6E / 3D DRAM



- 3D scaling
- Finer pitch
- More CMP & clean
- Higher materials complexity

70+ Engagements

POR WINS

- Next-Generation Metal-Oxide Resist
- Critical Ion Implant steps
- HBM4E CMP Slurries and Pads

NEW SAM EXPANSION

- $4F^2$ and 3D DRAM Materials
- Word Line and Bit Line Metallization
- Highly Selective SiGe and Si Etchants

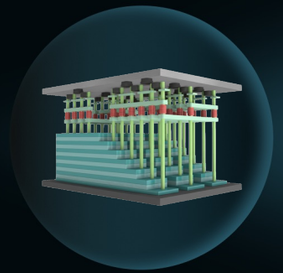
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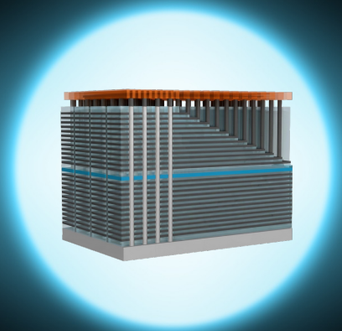
3 ADVANCED 3D NAND: +90% MORE CONTENT PER WAFER & NEW SAMS

TECHNOLOGY INFLECTIONS

300L



500-1,000L



HORIZONTAL CHANNEL FLASH (HCF)



- More layers
- Deeper channels
- More process steps

100+ Engagements

POR WINS

- Highly Selective Nitride Etch
- Word Line Mo Deposition
- Sacrificial Hard Mask CMP

NEW SAM EXPANSION

- Cryogenic Memory Hole Etch Gas
- Hybrid Bonding CMP

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3 INTEGRATED MOLYBDENUM SOLUTIONS ENABLING 3D NAND

ENTEGRIS PROVIDES THE INTEGRATED MATERIALS AND DELIVERY PLATFORM FOR MOLY DEPOSITION

MATERIALS



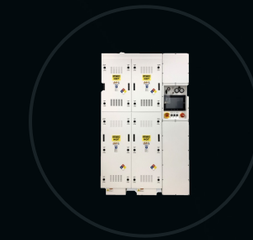
MoO_2Cl_2 molecule, Mo precursor chemistry

DELIVERY



ProE-Vap® canister + specialty coatings

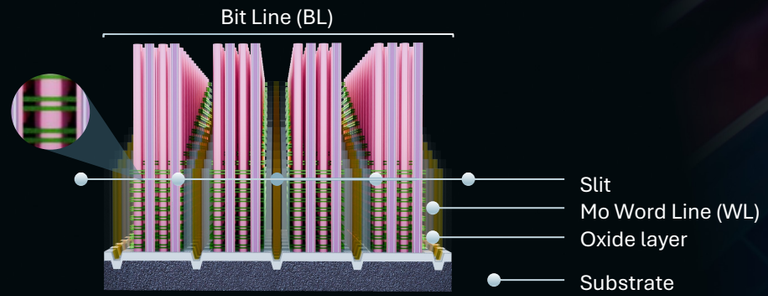
DELIVERY SYSTEM



Solid-state delivery cabinet

MOLY IS CRITICAL FOR NAND LAYER SCALING

Mo Word Lines replace Tungsten to reduce resistance as the stack scales



CUSTOMER ADOPTION SCALING

4 PORs

~2X YOY VOLUME GROWTH

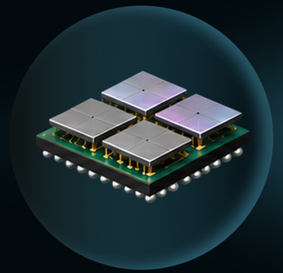
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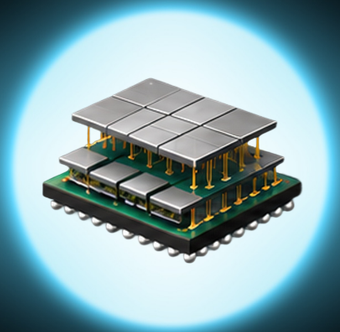
4 ADVANCED PACKAGING: +70% MORE CONTENT PER WAFER & NEW SAMS

TECHNOLOGY INFLECTIONS

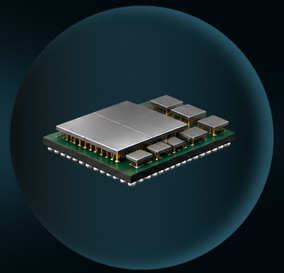
2.5D HETEROGENEOUS INTEGRATION



3D + LARGE-FORMAT INTEGRATION



SYSTEM-LEVEL HETEROGENEOUS INTEGRATION



- Larger area / more interfaces
- Finer pitch bonding
- Greater thermal density
- More materials-critical steps

55+ Engagements

POR WINS

- TSV and RDL CMP Solutions
- Dielectric Slurries For Carrier Removal
- TSV and RDL PERR Cleans

NEW SAM EXPANSION

- Wafer Thinning Wet Etch and Cleans
- 2.5D/3D Hybrid Bonding CMP Solutions
- Thermal Interface & Substrate Materials

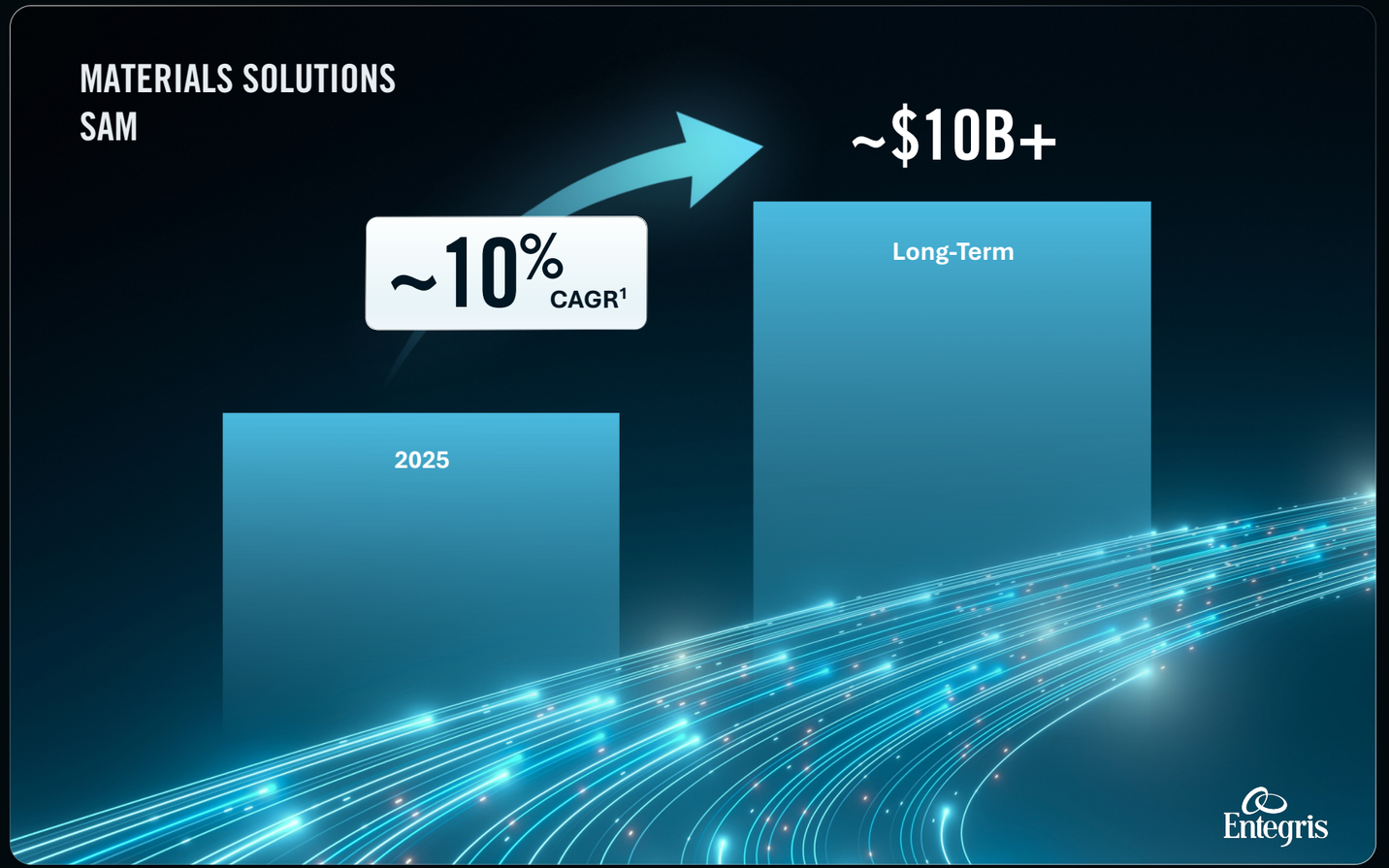
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TECHNOLOGY INFLECTIONS EXPAND MATERIALS SOLUTIONS SAM AT ~2X MSI GROWTH

SAM GROWTH IS DRIVEN BY RISING SEMICONDUCTOR MATERIALS REQUIREMENTS

- MORE STACKED LAYERS
- MORE PROCESS STEPS
- NEW MATERIALS



1. Long-Term (3-5 years).

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MS TRANSFORMATION CONVERTS OPPORTUNITY INTO RESULTS

THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM

CUSTOMER

ELEVATE CUSTOMER CENTRICITY

Co-Development
& Pathfinding



TECHNOLOGY

EXTEND TECHNOLOGY LEADERSHIP

100% AI-NPDs
3x faster cycles



OPERATIONS

STRATEGIC OPERATING SCALE

Advanced Process
Control Ready



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CUSTOMER + TECHNOLOGY

MOMENTUM ACCELERATING IN CUSTOMER ENGAGEMENT & INNOVATION

1

EARLIER QUALIFICATIONS

~2.5x

2

POR CONVERSION

~2.5x

3

VITALITY[1] = NEW PRODUCT REVENUE

~35%

1. Revenue from products released in the last 5 years as % of total for Materials Solutions.

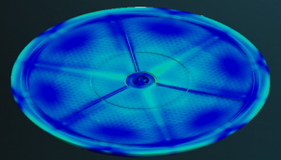
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TECHNOLOGY + SCALE

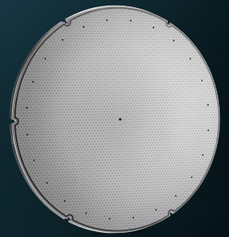
AI DRIVING STEP-CHANGE IN INNOVATION SPEED & MANUFACTURING QUALITY

LEADERSHIP IN AI MODELING & SIMULATION

E-CHUCK CASE STUDY



>30%
process improvements[1]



IMPROVE E-CHUCK EDGE-COOLING PERFORMANCE AND THERMAL DEFORMATION

LEADERSHIP IN MANUFACTURING QUALITY



BETTER DATA + EARLIER CONTROL = BETTER QUALITY AND YIELD

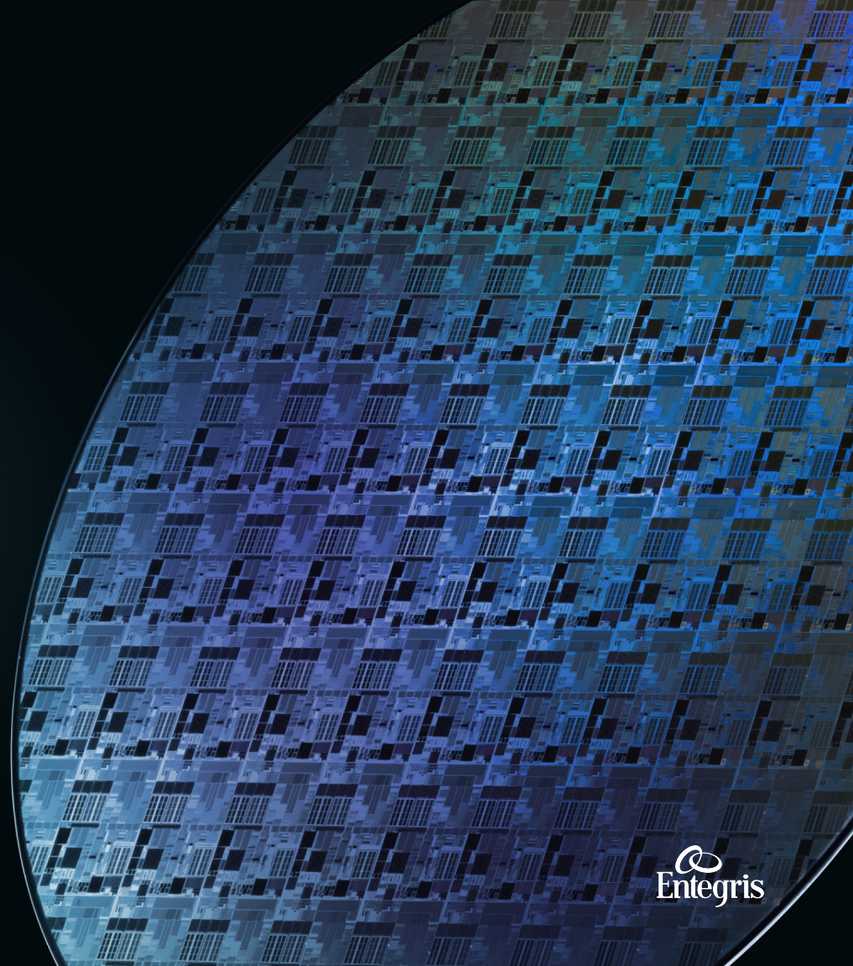
1. Lower max temperature, better thermal uniformity, lower deformation.

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MATERIALS SOLUTIONS IS POSITIONED FOR DOUBLE-DIGIT GROWTH AND MARGIN EXPANSION

AI DEVICE COMPLEXITY + TECHNOLOGY SOLUTIONS + DISCIPLINED EXECUTION = 13-15% GROWTH CAGR[1]



1. Long-Term (3-5 years).

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CLINT HARIS

SVP & President, Advanced Purity Solutions

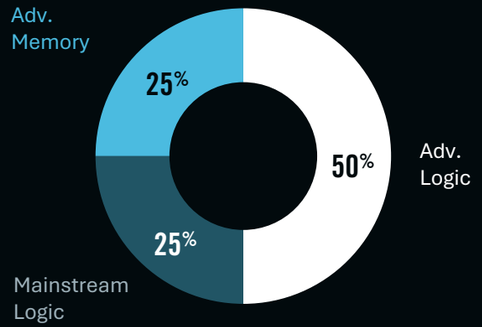
ADVANCED PURITY ENABLING YIELD & SCALE

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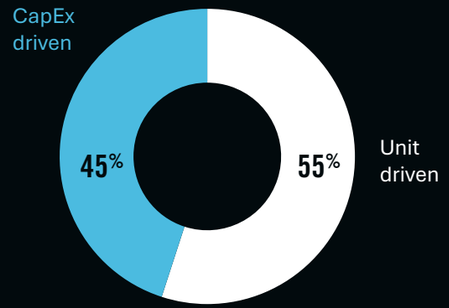
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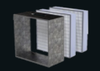
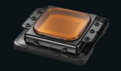
ADVANCED PURITY SOLUTIONS IS THE INDUSTRY'S ~$2B MISSION-CRITICAL PURITY PLATFORM

REVENUE BY **END MARKET**[1]
LTM



REVENUE BY **TYPE**[1]
LTM



LIQUID MICROCONTAMINATION CONTROL	 LIQUID PURIFIERS	 CMP FILTERS	 PHOTO FILTERS
GAS MICROCONTAMINATION CONTROL	 AMC FILTERS	 GAS PURIFICATION	 GAS FILTRATION
MICROENVIRONMENTS	 FOUPS	 RETICLE POD	 SHIPPERS & CARRIERS
FLUID MANAGEMENT & TRANSPORT	 FLUID HANDLING	 LIQUID PACKAGING	 DISPENSE PUMPS

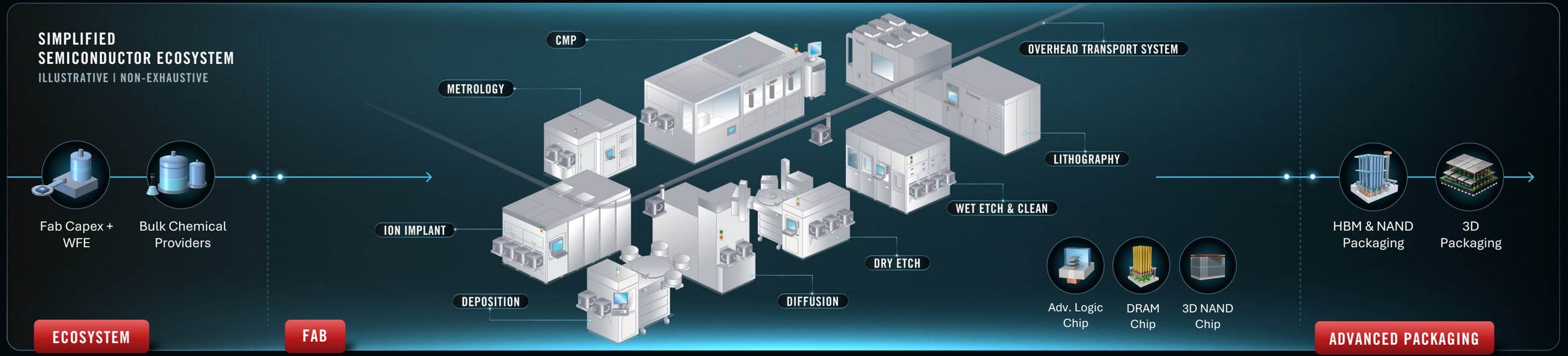
1. Percentages are approximate and based on management estimates, and exclude non-semiconductor revenue, which represents approximately 5% of LTM net sales.

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TECHNOLOGY

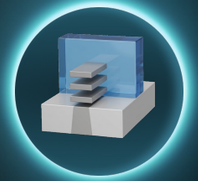
A TECHNOLOGY PORTFOLIO THAT COVERS THE ENTIRE SEMICONDUCTOR ECOSYSTEM



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THE INDUSTRY DEMANDS UNPRECEDENTED LEVELS OF CONTAMINATION CONTROL

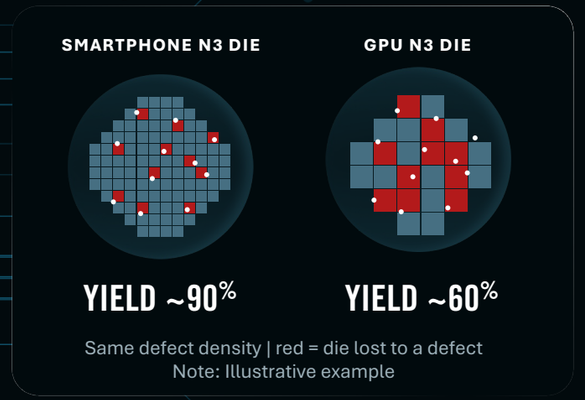
	CURRENT	NEAR-TERM	LONG-TERM
	FINFET	GAA + BSPDN	CFET
			
PURITY MEASUREMENT	PURITY REQUIREMENT	PURITY REQUIREMENT	
1  Particle Counts[1]		~10x	
2  Metal/Ionic Contamination[2]		~65x	
3  High Molecular Weight Organic Impurity[3]		~25x	

Source: SEMI standards, IRDS Roadmap, Entegris. 1. Point of process, 20nm/mL. 2. ppt. 3.ppb.

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1 ENTEGRIS ADVANCED FILTRATION IMPROVES YIELD



INDUSTRY CHALLENGE

Larger dies and smaller nodes demand lower defect density

More layers and process steps increase particle exposure and defect risk

Broader contamination types demand increasingly stringent purity control

COMPETITION

X PARTICLES PER WAFER

ENTEGRIS SOLUTION

Torrento®X for particle control in aggressive chemical applications

Astera™ for particle control in diluted chemical applications

Protego® purifier for contaminant removal

ENTEGRIS

<0.3X PARTICLES PER WAFER

Note: Based on Entegris internal testing; results may vary.

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2 ENTEGRIS DELIVERS PERFORMANCE ADVANTAGES

PROTEGO® SM5 ULTRACLEAN PURIFIER



TORRENTO® X LIQUID FILTER



INDUSTRY CHALLENGE

Semiconductor chemicals require ppt-level control of dissolved metals

Contaminant behavior varies, limiting conventional filtration

COMPETITION

10–30 PPT Fe in IPA

ENTEGRIS SOLUTION

Protego® ion-exchange media captures dissolved metals

Torrento®X filtration membranes remove particulate and colloidal metals

ENTEGRIS

1–3 PPT After Entegris purification

Note: Based on Entegris internal testing; results may vary.

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3 ENTEGRIS DELIVERS PERFORMANCE ADVANTAGES

FOUP EBM A300



INDUSTRY CHALLENGE

Increasing sensitivity to moisture, oxygen, and airborne molecular contaminants

Door-open airflow limits conventional FOUP purge effectiveness on process tools

COMPETITION

20-40% RELATIVE HUMIDITY

During open-door purge

ENTEGRIS SOLUTION

Advanced purge-flow diffusers enable more uniform purge distribution

Entegris Barrier Material (EBM) reduces water contamination

ENTEGRIS

<5% RELATIVE HUMIDITY

With Entegris purge

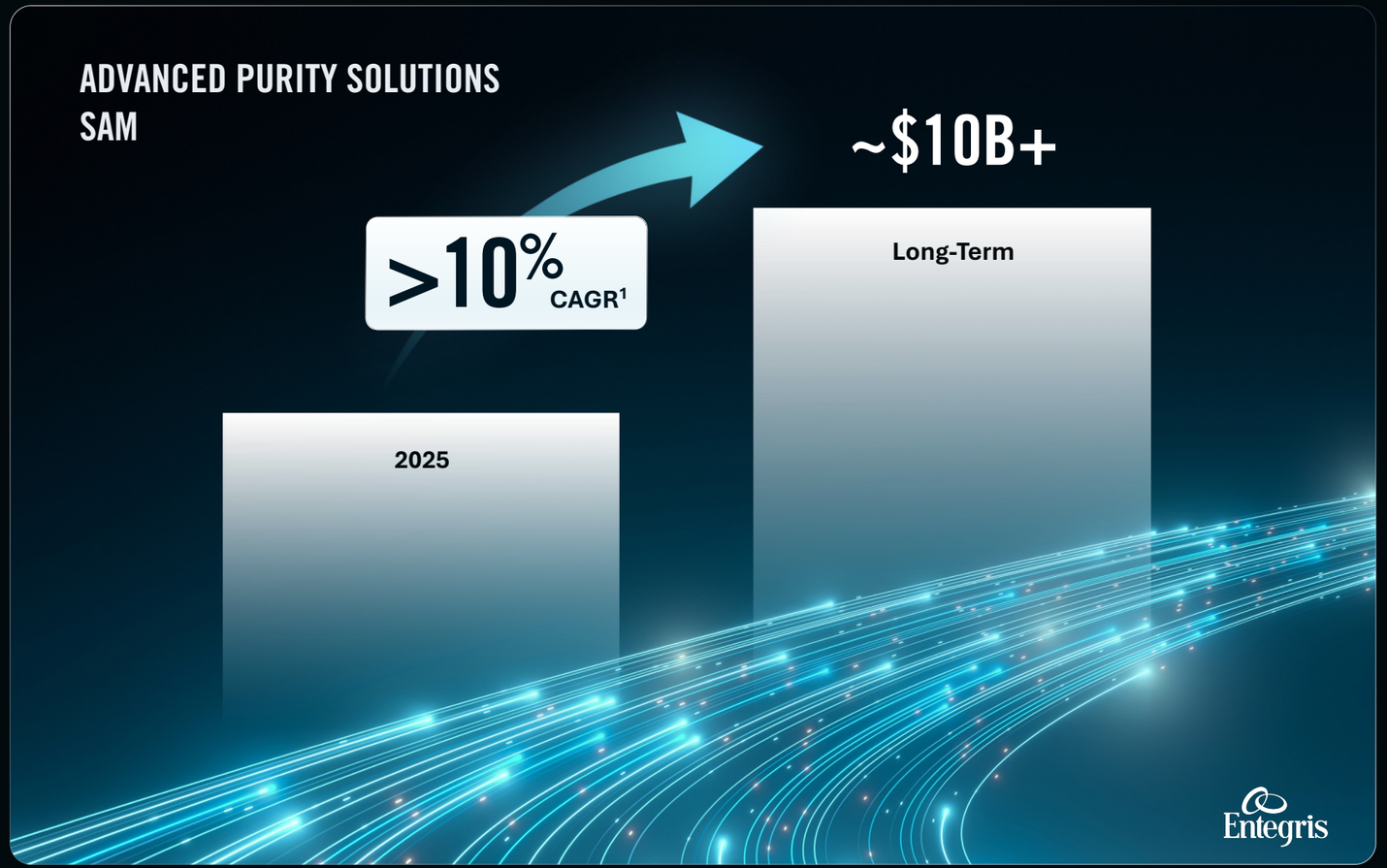
Note: Based on Entegris internal testing; results may vary.

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INCREASING PURITY REQUIREMENTS DRIVE >10% SAM GROWTH CAGR

SAM GROWTH IS DRIVEN BY RISING SEMICONDUCTOR PURITY REQUIREMENTS

- TIGHTER PURITY REQUIREMENTS
- INCREASED CONTROL POINTS
- NEW CONTAMINANT CLASSES



1. Long-Term (3-5 years).

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APS TRANSFORMATION CONVERTS OPPORTUNITY INTO RESULTS

THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM

CUSTOMER

ELEVATE CUSTOMER CENTRICITY

Partner across entire ecosystem to bring complete solutions



TECHNOLOGY

EXTEND TECHNOLOGY LEADERSHIP

Accelerate concept-to-product cycles via AI modeling & simulation



OPERATIONS

STRATEGIC OPERATING SCALE

AI implementation to improve productivity and yield at scale



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CUSTOMER + TECHNOLOGY

CO-DEVELOPMENT AND FASTER INNOVATION DRIVES MORE DESIGN WINS

CUSTOMER CENTRICITY

Partner across ecosystem for complete customer solutions

Resist suppliers	Defect-free coating chemistries
Tooling companies	Process integration requirements
Chip manufacturers	Wafer yield requirements

LITHOGRAPHY MODULE



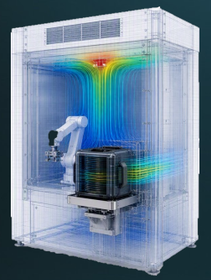
OPTIMIZED SOLUTION

INCREASED CUSTOMER SATISFACTION

TECHNOLOGY LEADERSHIP

AI enabled modeling and simulation to deliver solutions faster

FOUP CFD DIGITAL TWIN



Design faster in software

Build



QUALIFIED NEXT-GEN FOUP

CONDENSED CONCEPT-TO-PRODUCT INNOVATION CYCLE

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OPERATIONS

TRANSFORMING MANUFACTURING TO DRIVE PRODUCTIVITY AND YIELD

MAXIMIZING INSTALLED-BASE PRODUCTIVITY



FOCUSED “IN-REGION, FOR-REGION” MANUFACTURING CAPACITY



SCALING AI FOR HIGHER YIELD

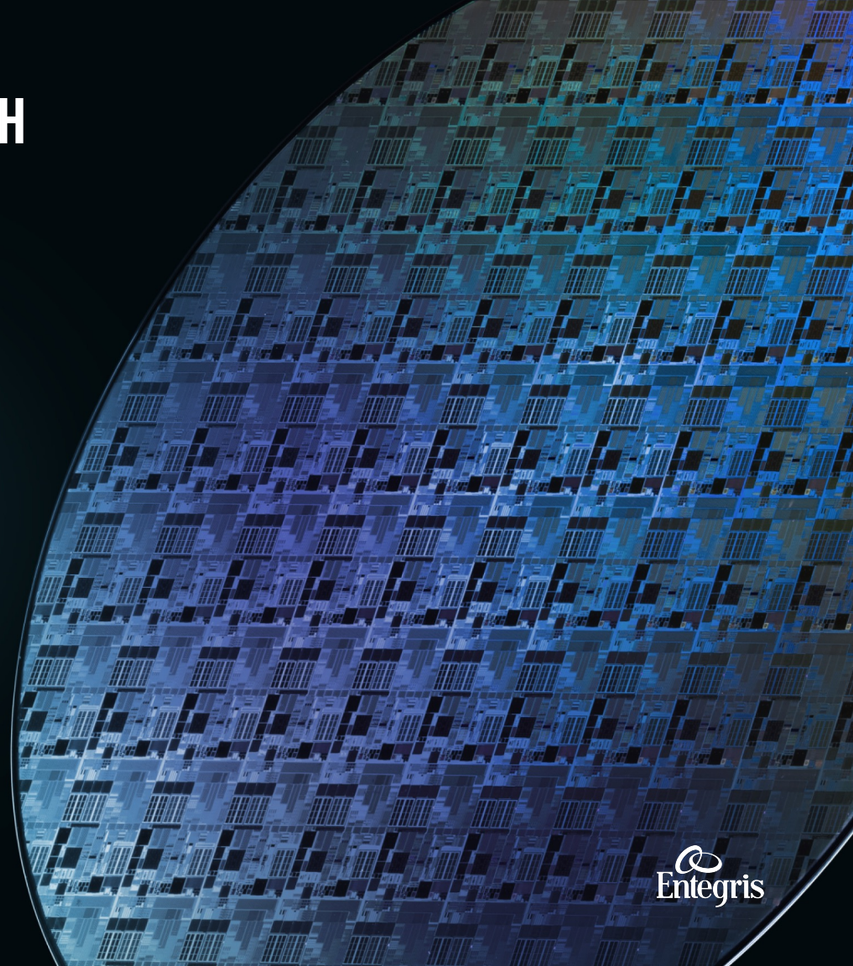


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ADVANCED PURITY SOLUTIONS IS POSITIONED FOR DOUBLE-DIGIT GROWTH AND MARGIN EXPANSION

AI DEVICE COMPLEXITY + TECHNOLOGY SOLUTIONS + DISCIPLINED EXECUTION = 15-17% GROWTH CAGR[1]



1. Long-Term (3-5 years).

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SUKHI NAGESH

SVP, CFO

COMPOUNDING GROWTH, PROFITABILITY, AND SHAREHOLDER VALUE

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THE ENTEGRIS VALUE CREATION FRAMEWORK



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OUR TRANSFORMATION IS DELIVERING RESULTS

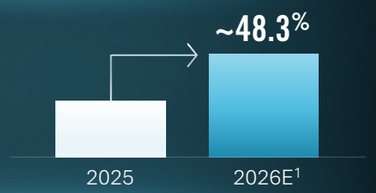
REVENUE

+17% YoY



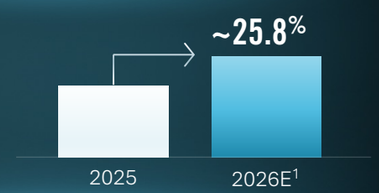
ADJ. GROSS MARGIN

+370 bps



ADJ. OPERATING MARGIN

+450 bps



ADJ. EPS

+59% YoY



CAPEX
% OF SALES

~6% of sales



NET LEVERAGE

~2.7x

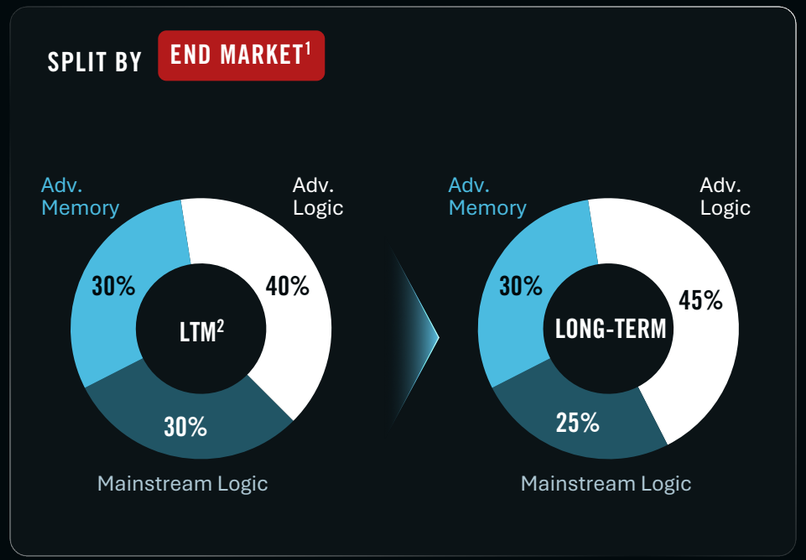


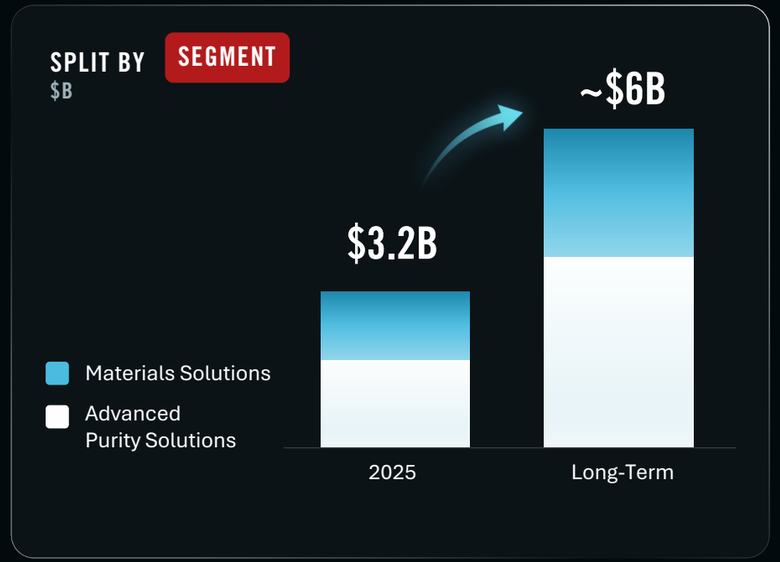
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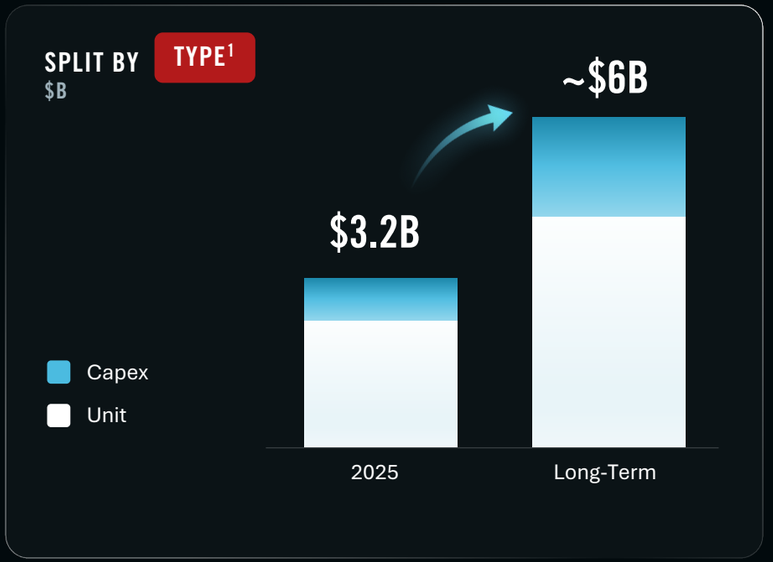
1. Midpoint of the 4Q26 guidance range. Note: See GAAP to non-GAAP reconciliation tables in the appendix.

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ADVANCED MANUFACTURING EXPOSURE SUPPORTS ~15% REVENUE CAGR





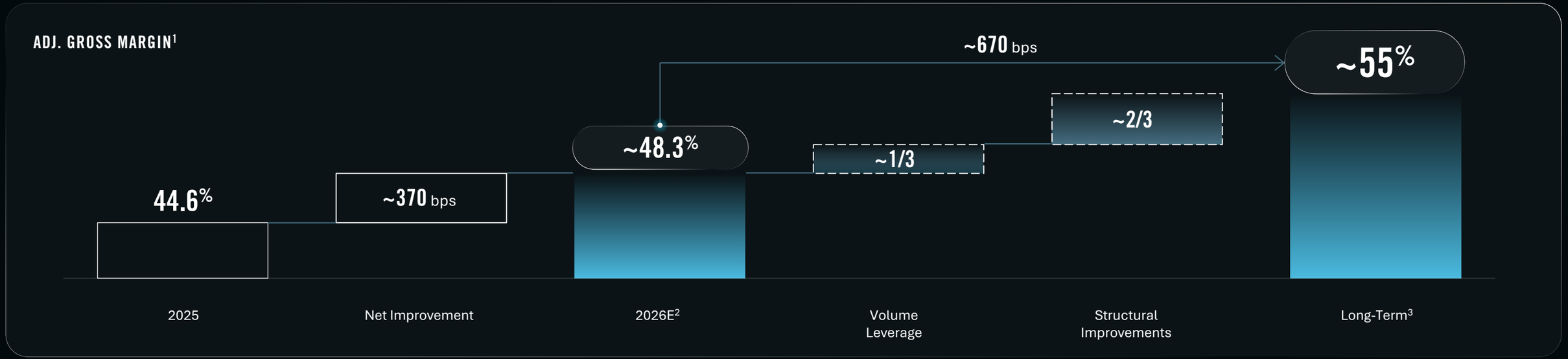


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1. Percentages are approximate and based on management estimates, and exclude non-semiconductor revenue, which represents approximately 5% of LTM net sales. 2.Last 12 months as of 3Q26.

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EXECUTION DELIVERING SIGNIFICANTLY HIGHER PROFITABILITY

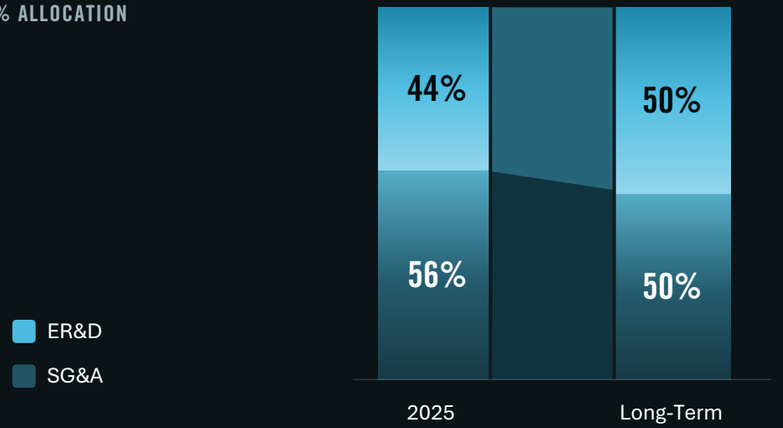


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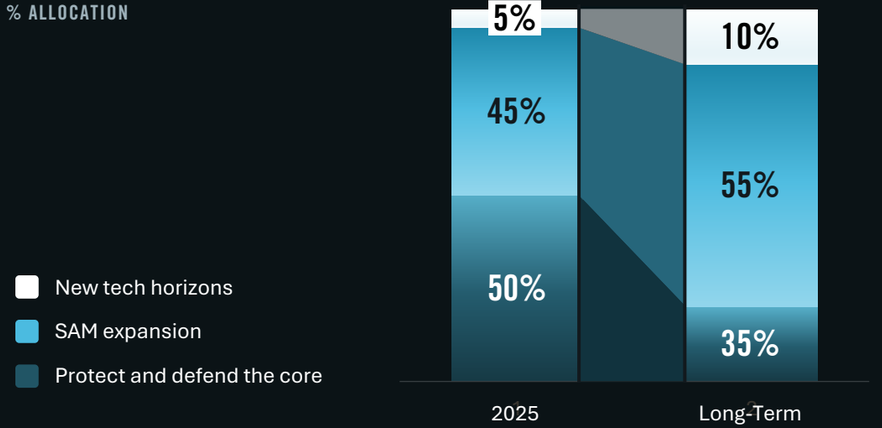
1. See GAAP to non-GAAP reconciliation tables in the appendix of this presentation. 2. At the midpoint of 4Q26 guidance range. 3. Forward-looking non-GAAP metric; not reconciled.

EXPANDING ADJ. OPERATING MARGINS WHILE CONTINUING TO INVEST IN INNOVATION

ADJ. OPERATING EXPENSES[1]
% ALLOCATION



ADJ. ER&D INVESTMENT[1]
% ALLOCATION





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1. See GAAP to non-GAAP reconciliation tables in the appendix of this presentation. Long-term (3-5 years). 2. Forward-looking non-GAAP metric; not reconciled.
Note: ~35% reflects consolidated Adj. Operating Margin Target based on APS (~40%) and MS (~30%) over 3-5 years.

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ACCELERATING FCF[1] GROWTH

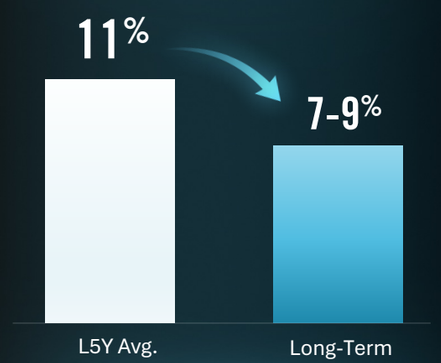
We are driving cash conversion efficiency...

CASH CONVERSION CYCLE[2]
(DAYS)



...While remaining disciplined with CapEx...

CAPEX AS % OF SALES



...Leading to:

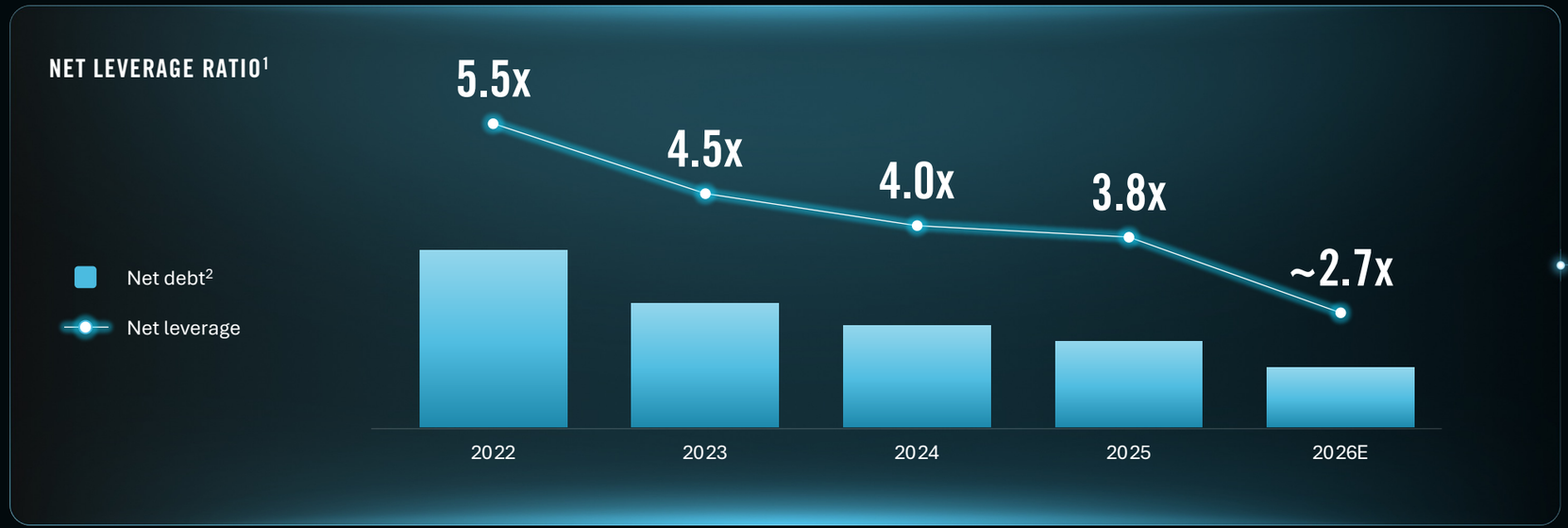
FCF GROWTH > REVENUE GROWTH

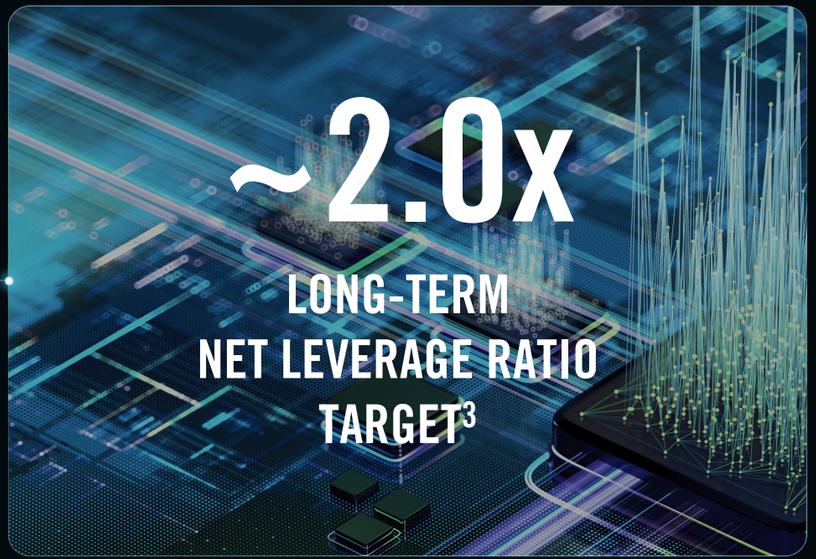
1. Free Cash Flow ("FCF") defined as Cash From Operations less capital expenditures net of government incentives. Long-Term (3-5 years). 2. Cash Conversion Cycle: days inventory outstanding plus days sales outstanding less days payable outstanding, calculated using average balance-sheet balances and the income statement activity for the trailing 3 months. Long-Term (3-5 years).

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CONTINUED DELEVERAGING INCREASES CAPITAL ALLOCATION FLEXIBILITY





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1. Net Leverage Ratio defined as gross debt less cash and cash equivalents divided by trailing 12-months adj. EBITDA (see GAAP to non-GAAP reconciliation tables in the appendix of this presentation).
2.Net debt defined as gross debt less cash and cash equivalents. 3. Forward-looking non-GAAP metric; not reconciled. Long-Term (3-5 years).

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BALANCED CAPITAL ALLOCATION MAXIMIZES LONG-TERM VALUE CREATION



INVEST IN THE BUSINESS

Organic ER&D
and CapEx



STRATEGIC M&A

Strengthen and expand
our portfolio



SHAREHOLDER RETURNS

Return ~50% of excess cash
to shareholders

BALANCE SHEET STRENGTH ENABLES OUR CAPITAL ALLOCATION PRIORITIES

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THE POWER OF ENTEGRIS' LONG-TERM GROWTH ALGORITHM

~15%	~55%	~35%	~30%
Revenue CAGR	Adj. Gross Margin	Adj. Operating Margin	Adj. EPS CAGR

ENTEGRIS: THE INDUSTRY'S LEADING PURE-PLAY MATERIALS AND PURITY PLATFORM

Long-Term (3-5 years).

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THANK YOU



GLOSSARY

ABBREVIATION	FULL FORM
3D NAND	Three-Dimensional Not-AND
$4F^2$	4 times the square of the minimum feature size
AI/ML	Artificial Intelligence / Machine Learning
ALD	Atomic Layer Deposition
ALE	Atomic Layer Etching
AMC	Airborne Molecular Contamination
ASD	Area-Selective Deposition
ATMI	Advanced Technology Materials, Inc.
bps	Basis Points
BSPDN	Backside Power Delivery Network
CFD	Computational Fluid Dynamics
CFET	Complementary Field-Effect Transistor
CMC	Cabot Microelectronics Corporation
CMP	Chemical Mechanical Planarization
CPO	Co-Packaged Optics
CRP	Clean Room Plastics Inc
CVD	Chemical Vapor Deposition
DRAM	Dynamic Random-Access Memory
e-chucks	Electrostatic Chucks

ABBREVIATION	FULL FORM
EUV	Extreme Ultraviolet
Fe	Iron
FEOL	Front-End-of-Line
FinFET	Fin Field-Effect Transistor
FOUP	Front Opening Unified Pod
GAA	Gate-All-Around
GaN	Gallium Nitride
GMTI	Global Measurement Technologies Inc
HBM	High Bandwidth Memory
HCF	Horizontal Channel Flash
HVAC	Heating, Ventilation, and Air Conditioning
IC	Integrated Circuit
IDM	Integrated Device Manufacturer
IPA	Isopropyl Alcohol
KSP	Kaohsiung Science Park
Mo	Molybdenum
MoO2Cl2	Molybdenum Dioxide Dichloride
MSI	Million Square Inches

ABBREVIATION	FULL FORM
NPDs	New Product Developments
OEM	Original Equipment Manufacturer
OSAT	Outsourced Semiconductor Assembly and Test
PC	Personal Computers
POR	Process of Record
ppb	parts per billion
ppt	parts per trillion
PVD	Physical Vapor Deposition
RDL	Redistribution Layer
RF	Radio Frequency
SAES	Società Apparecchi Elettrici e Scientifici
SAM	Served Available Market
SiC	Silicon Carbide
SiGe	Silicon-Germanium
TAM	Total Available Market
TIM	Thermal Interface Material
TSV	Through-Silicon Via
WFE	Wafer Fab Equipment

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FINANCIAL APPENDIX

CAPITAL MARKETS DAY 2026

RECONCILIATION OF GROSS PROFIT TO ADJUSTED GROSS PROFIT[1]

$ IN MILLIONS	FY2025	FY2026E
Net Sales	$3,196.6	$3,740.8
Gross profit – GAAP	$1,419.9	$1,815.8
Adjustments to gross profit:		
IEEPA tariff refunds [J]	-	(8.3)
Restructuring costs [K]	4.3	0.7
Adjusted Gross profit	$1,424.2	$1,808.2
Gross margin - as a % of net sales	44.4%	48.5%
Adjusted Gross margin - as a % of net sales	44.6%	48.3%

GAAP TO NON-GAAP OPERATING EXPENSE RECONCILIATION[1]

$ IN MILLIONS	FY2025					FY2025	
	GAAP	% OF TOTAL	RESTRUCTURING COSTS [K]	LOSS FROM SALE OF BUSINESS [P]	AMORTIZATION OF INTANGIBLE ASSETS [Q]	NON-GAAP	% OF TOTAL
Selling, general & administrative	$450.6	47%	($21.8)	($10.9)		$417.9	56%
Engineering, research & development	$329.0	34%	($3.6)			$325.4	44%
Amortization expense	$184.4	19%			($184.4)	-	-
Total operating expense	$964.0	100%	($25.4)	($10.9)	($184.4)	$743.3	100%

1. See footnotes section for reference of adjustments.

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RECONCILIATION OF GAAP NET INCOME TO ADJUSTED OPERATING INCOME AND ADJUSTED EBITDA[1]

$ IN MILLIONS	FY2022	FY2023	FY2024	FY2025	FY2026E
Net Sales	$3,282.0	$3,523.9	$3,241.2	$3,196.6	$3,740.8
Net income	208.9	180.7	292.8	235.6	517.8
Net income - as a % of net sales	6.4%	5.1%	9.0%	7.4%	13.8%
Adjustments to net income:					
Income tax expense (benefit)	38.2	(8.4)	28.3	18.0	72.3
Interest expense, net	209.0	301.1	207.9	191.9	177.6
Other expense, net	23.9	25.4	4.0	9.4	11.4
Equity in net loss of affiliates	—	0.4	0.9	1.0	0.2
GAAP - Operating income	$480.0	$499.2	$533.9	$455.9	$779.3
Operating margin - as a % of net sales	14.6%	14.2%	16.5%	14.3%	20.8%
Goodwill Impairment [A]	—	115.2	—	—	—
Deal and transaction costs [B]	39.5	3.0	—	—	—
Integration costs					
Professional fees [C]	35.4	36.7	2.6	—	—
Severance costs [D]	6.3	1.5	0.8		
Retention costs [E]	2.0	1.7	—	—	—
Other costs [F]	7.1	13.7	—	—	—
Contractual and non-integration costs					
CMC Materials retention costs [H]	18.0	—	—	—	—
Stock-based compensation alignment [I]	21.6	—	—	—	—
Change in control costs [G]	22.4	—	—	—	—
IEEPA Tariff refunds [J]	—	—	—	—	(8.3)
Restructuring costs [K]	—	14.7	3.9	29.7	11.2
Acquired tax equalization asset reduction [L]	—	—	3.0	—	—
Impairment of long-lived assets [M]	—	30.5	13.0	—	—
Charge for fair value write-up of acquired inventory sold [N]	61.9	—	—	—	—
Gain on termination of Alliance Agreement [O]	—	(184.8)	—	—	—
(Gain) loss from sale of businesses [P]	(0.3)	23.8	(4.3)	10.9	—
Amortization of intangible assets [Q]	144.0	214.5	190.1	184.4	183.3
Adjusted operating income	$837.9	$769.7	$743.0	$680.9	$965.5
Adjusted operating margin - as a % of net sales	25.5%	21.8%	22.9%	21.3%	25.8%
Depreciation	135.4	172.7	188.1	205.3	136.7
Adjusted EBITDA	$973.2	$942.4	$931.1	$886.2	$1,102.2
Adjusted EBITDA - as a % of net sales	29.7%	26.7%	28.7%	27.7%	29.5%

1. See footnotes section for reference of adjustments. As a result of displaying amounts in millions, rounding difference may exist in this table.

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RECONCILIATION OF GAAP NET INCOME AND DILUTED EARNINGS PER COMMON SHARE TO NON-GAAP NET INCOME AND DILUTED NON-GAAP EARNINGS PER COMMON SHARE[1]

$ IN MILLIONS, EXCEPT PER SHARE DATA	FY2025	FY2026E
GAAP net income	$235.6	$517.8
Adjustments to net income:		
IEEPA Tariff refunds [J]	—	(8.3)
Restructuring costs [K]	29.7	11.2
Equity investment impairment [R]	—	6.7
Loss from the sale of business [P]	10.9	—
Amortization of intangible assets [Q]	184.4	183.3
Loss on extinguishment of debt [S]	3.2	3.9
Tax effect of adjustments to net income and discrete items	(45.3)	(40.8)
Non-GAAP net income	$418.5	$673.8
Diluted earnings per common share	$1.55	$3.37
Effect of adjustments to net income	$1.20	$1.01
Diluted non-GAAP earnings per common share	$2.75	$4.38

1. See footnotes section for reference of adjustments.

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FOOTNOTES

A. **Goodwill impairment.** Non-cash impairment charges associated with goodwill.

B. **Deal and transaction costs.** Deal and transaction costs associated with the CMC Materials acquisition and completed and announced divestitures.

C. **Integration costs – Professional Fees.** Represents professional and vendor fees recorded in connection with services provided by consultants, accountants, lawyers and other third-party service providers to assist us in integrating CMC Materials into our operations.

D. **Integration costs – Severance costs.** Represent severance charges related to the integration of the CMC Materials acquisition.

E. **Integration costs – Retention costs.** Represents retention charges related directly to the CMC Materials acquisition and completed and announced divestitures, and are not part of our normal, recurring cash operating expenses.

F. **Integration costs – Other costs.** Represents other employee related costs and other costs incurred relating to the CMC Materials acquisition and completed and announced divestitures. These costs arise outside of the ordinary course of our continuing operations.

G. **Contractual and non-integration costs – Change in control costs.** Relates to the change in control agreements that were in place with management of CMC Materials prior to the acquisition and the associated expense post-acquisition.

H. **Contractual and non-integration costs – CMC Materials Retention costs.** Represents non-recurring costs associated with the CMC Materials retention program that was agreed upon and set forth in the definitive acquisition agreement.

I. **Contractual and non-integration costs – Stock-based compensation alignment.** Represents the non-cash incremental expense associated with adopting retirement vesting obligations on Entegris equity awards, similar to those of CMC Materials equity awards.

J. **IEEPA Tariff refunds.** In the three months ended September, 26, 2026, the Company received $8.3 million of refunds of International Emergency Economic Powers Act (IEEPA) tariffs that were recognized in cost of goods sold as incurred from April 2025 through February 2026 and were not excluded from the Company's non-GAAP results in those periods. The Company excluded the refunds from non-GAAP results because they represent a discrete, non-recurring, out-of-period recovery arising from a legal and regulatory development rather than ongoing operating performance

K. **Restructuring costs.** Restructuring charges resulting from cost-saving initiatives.

L. **Acquired tax equalization asset reduction.** Represents an asset reduction of an acquired tax equalization asset from the CMC Materials acquisition.

M. **Impairment of long-lived assets.** Non-cash charges recognized to write down long-lived assets to their estimated fair values.

N. **Charge for fair value write-up of acquired inventory sold.** Represents the additional cost of goods sold recognized in connection with the step-up of inventory valuation from the CMC acquisition.

O. **Gain on termination of Alliance Agreement.** Gain on termination of Alliance Agreement with MacDermid Enthone.

P. **(Gain) loss from sale of businesses.** The (gain)loss recognized upon the divestiture of certain businesses.

Q. **Amortization of intangible assets.** Non-cash amortization expense associated with intangibles acquired in acquisitions.

R. **Equity investment impairment.** Equity investment impairment loss in 2026 that reduced our carrying basis to zero.

S. **Loss on extinguishment of debt.** Loss on extinguishment of debt of our Term Loan Facility.

T. **Tax effect of adjustments to net income and discrete items.** The tax effect of pre-tax adjustments to net income was calculated using the applicable marginal tax rate for each respective year.

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